## Single Chip Field Reprogrammable Battery Manager Nickel Chemistries

- Single chip solution for rechargeable battery management
- Footprint compatible with PS402
- SMBus 1.1 and SBData 1.1 compatible
- Precise capacity reporting for NiMH and NiCd battery chemistries
- Embedded Microchip patented Accuron ${ }^{\circledR}$ technology contained in customizable on-chip 16-Kbyte Flash memory
- User configurable and "learned" parameters stored in on-chip $256 \times 8$ EEPROM
- Algorithms and parameters fully field reprogrammable via SMBus interface
- Integrating sigma-delta A/D converter with 9 to 16-bit programmable resolution which accurately measures:
- Current through sense resistor
- High-voltage (18V) battery cells directly connected to VcELL inputs
- Temperature measurement from on-chip sensor or optional external thermistor
- Integrated precision silicon time base
- Twelve individually programmable input/output pins that can be assigned as charge control I/O, secondary safety function I/O, SOC LED output or general purpose I/O
- Two of the twelve I/Os are high-voltage, capable for direct drive of charge and safety FETs
- On-chip regulator generates precision digital and analog supply voltages directly from pack voltage
- Flexible power operating modes:
- Run: Continuous operation
- Sample: Periodic measurements at programmable intervals
- Sleep: Shutdown mode due to low voltage; power consumption less than $25 \mu \mathrm{~A}$
- Shelf-Sleep: Shuts off PS501-0901 power consumption for pack storage with automatic wake-up on pack insertion; power consumption is less than $1 \mu \mathrm{~A}$
- Integrated Reset Control
- Power-on Reset
- Watchdog Timer Reset
- Brown-out Detection Reset


## Pin Description



## Pin Summary

| Pin Name | Type | Description |
| :--- | :---: | :--- |
| VDDD, VSSD | Supply | Digital supply voltage input, <br> ground |
| GPIO(0..9) | I/O | Programmable digital I/O |
| GPIOHV1,2 | I/O | Open-drain programmable <br> digital I/O for direct drive of <br> FETs |
| $\overline{\text { MCLR }}$ | I | Master Clear; pull-up in <br> normal operation |
| SMB-CLK, <br> SMB-DTA | I/O | SMBus interface <br> VC(1) |
| I | Pack voltage input |  |
| VDDA, VSSA | Supply | Voltage regulator output <br> (internally connected to <br> analog supply input); ground |
| RSHP, RSHN | I | Current sense resistor input |
| VNTC | I | External thermistor input |
| VREFT | O | Thermistor reference voltage |
| ROSC | I | Internal oscillator bias resistor |
| RSV1 -3 | I | Reserved pins |

### 1.0 PRODUCT OVERVIEW

The PS501-0901 combines a high-performance, lowpower Microchip PIC18 microcontroller core, together with PowerSmart ${ }^{\text {® }}$ proprietary monitor/control algorithms and 3D cell models, stored in 16 Kbytes of on-chip reprogrammable Flash memory.

Analog resources include a 16-bit sigma-delta integrating $A / D$ and mixed signal circuitry for precision measurement of battery current, temperature and voltage. On-chip EEPROM is provided for storage of user customizable and "learned" battery parameters.

An industry standard 2-wire SMBus interface supports host communication using standard SBData commands and status.

Additional integrated features include a high accuracy on-chip oscillator and temperature sensor. Twelve general purpose pins support charge or safety control or user programmable digital I/O. Eight of them can be used as LED drivers and two are open drain for direct FET drive.
The PS501-0901 can be configured to accommodate all Nickel rechargeable battery chemistries, including NiMH and NiCd. Nickel battery packs must contain between six and twelve series cells.

FIGURE 1-1: PS501-0901 INTERNAL BLOCK DIAGRAM


### 1.1 Architectural Description

The PS501-0901 is a a fully field reprogrammable single chip solution for rechargeable battery management. Figure $1-1$ is an internal block diagram highlighting the major architectural elements described below.

### 1.2 Microcontroller/Memory

The PS501-0901 incorporates an advanced, lowpower Microchip PIC18 8-bit RISC microcontroller core. Memory resources include 16 Kbytes of reprogrammable Flash memory for program/data storage and 256 bytes of EEPROM for parameter storage. Both memory arrays may be reprogrammed through the SMBus interface.

### 1.3 A/D Converter

The PS501-0901 performs precise measurements of current, voltage and temperature, using a highly accurate 16 -bit integrating sigma-delta $A / D$ converter. The $A / D$ can be calibrated to eliminate gain and offset errors and incorporates an auto-zero offset correction feature that can be performed while in the end system application.

### 1.4 Microchip Firmware/Battery Models

Contained within the 16-Kbyte Flash memory is the Microchip developed battery management firmware that incorporates proprietary algorithms and sophisticated 3-dimensional cell models. Developed by battery chemists, the patented, self-learning 3D cell models contain over 250 parameters and compensate for selfdischarge, temperature and other factors. In addition, multiple capacity correction and error reducing functions are performed during charge/discharge cycles to enhance accuracy and improve fuel gauge and charge control performance. As a result, accurate battery capacity reporting and run-time predictions with less than $1 \%$ error are achievable.
The reprogrammability of the Flash allows firmware upgrades and customized versions to be rapidly created without the need for silicon revisions.
The PS501-0901 can be easily customized for a particular application's battery cell chemistry. Standard configuration files are provided by Microchip for a wide variety of popular rechargeable cells and battery pack configurations.

### 1.5 SMBus Interface/SBData Commands

Communication with the host is fully compliant with the industry standard Smart Battery System (SBS) specification. Included is an advanced SMBus communications engine that is compliant with the SMBus v1.1 protocols. The integrated firmware processes all the revised Smart Battery Data (SBData) v1.1 values.

### 1.6 Accurate Integrated Time Base

The PS501-0901 provides a highly accurate RC oscillator that provides accurate timing for selfdischarge and capacity calculations and eliminates the need for an external crystal.

### 1.7 Temperature Sensing

An integrated temperature sensor is provided to minimize component count when the PS501-0901 IC is located in close physical proximity to the battery cells being monitored. As an option, a connection is provided for an external thermistor that can also be monitored.

### 1.8 General Purpose I/O

Twelve programmable digital input/output pins are provided by the PS501-0901. Eight of these pins can be used as LED outputs to display State-Of-Charge (SOC) or for direct control of external charge circuitry. Alternatively, they can be used as general purpose input/outputs. Two of the I/Os are open-drain outputs and can thus be used to directly drive FETs or other high-voltage applications.

## PS501-0901

TABLE 1-1: PIN DESCRIPTIONS

| Pin | Name | Description |
| :---: | :---: | :---: |
| 1 | Vddd | (Input) Filter capacitor input for digital supply voltage. |
| 2 | GPIO(4) | (Bidirectional) Programmable general purpose digital input/output pin (4) or LED driver. |
| 3 | GPIO(5) | (Bidirectional) Programmable general purpose digital input/output pin (5) or LED driver. |
| 4 | GPIO(6) | (Bidirectional) Programmable general purpose digital input/output pin (6) or LED driver. |
| 5 | GPIO(7) | (Bidirectional) Programmable general purpose digital input/output pin (7) or LED driver. |
| 6 | SMB-CLK | SMBus clock pin connection. |
| 7 | SMB-DTA | SMBus data pin connection. |
| 8 | RSV1 | Reserved - Must be connected to ground. |
| 9 | RSV2 | Reserved - Must be connected to ground. |
| 10 | RSV3 | Reserved - Must be connected to ground. |
| 11 | VC(1) | (Input) Pack voltage input. |
| 12 | VDDA | (Input) Analog supply voltage input. |
| 13 | VSSA | Analog ground reference point. |
| 14 | RSHP | (Input) Current measurement A/D input from positive side of the current sense resistor. |
| 15 | RSHN | (Input) Current measurement A/D input from negative side of the current sense resistor. |
| 16 | VNTC | (Input) A/D input for use with an external temperature circuit. This is the midpoint connection of a voltage divider where the upper leg is a thermistor (103ETB type) and the lower leg is a 3.65 kOhm resistor. This input should not go above 150 mV . |
| 17 | Vreft | (Output) Reference voltage output for use with temperature measuring A/D circuit. This 150 mV output is the top leg of the voltage divider and connects to an external thermistor. |
| 18 | Rosc | External bias resistor. |
| 19 | GPIO(8) | (Bidirectional) Programmable general purpose digital input/output pin (8). |
| 20 | GPIO(9) | (Bidirectional) Programmable general purpose digital input/output pin (9). |
| 21 | GPIOHV1 | (Bidirectional) Programmable general purpose digital input/output pin (10). Open-drain, high-voltage tolerant. |
| 22 | $\overline{\mathrm{MCLR}}$ | (Input) Master Clear. Must be pulled up for normal operation. |
| 23 | GPIOHV2 | (Bidirectional) Programmable general purpose digital input/output pin (11). Open-drain, high-voltage tolerant. |
| 24 | GPIO(0) | (Bidirectional) Programmable general purpose digital input/output pin (0) or LED driver. |
| 25 | GPIO(1) | (Bidirectional) Programmable general purpose digital input/output pin (1) or LED driver. |
| 26 | GPIO(2) | (Bidirectional) Programmable general purpose digital input/output pin (2) or LED driver. |
| 27 | GPIO(3) | (Bidirectional) Programmable general purpose digital input/output pin (3) or LED driver. |
| 28 | VSSD | Digital ground reference point. |

### 2.0 A/D OPERATION

The PS501-0901 A/D converter measures voltage, current and temperature and integrates the current over time to measure State-Of-Charge. The voltage of the entire pack is monitored and the pack is calibrated for accuracy. Using an external sense resistor, current is monitored during both charge and discharge and is integrated over time using the on-chip oscillator as the time base. Temperature is measured from the on-chip temperature sensor or an optional external thermistor. Current and temperature are also calibrated for accuracy.

### 2.1 A/D Converter List

The A/D converter alternately measures pack voltage, current, temperature and auto-offset as explained below. The schedule for the sequence and frequency of these measurements is programmable, as is the number of bits used. The default scheduling uses four lists. At near full (above the voltage point ADLNearFull) and near empty (below the voltage point ADLNearEmpty), voltage intensive lists are used to accurately end charge or discharge. In between ADLNearFull and ADLNearEmpty, a current intensive schedule is used to more accurately calculate capacity.

### 2.2 Current Measurement

The A/D input channels for current measurement are the RSHP and RSHN pins. The current is measured using an integrating method, which averages over time to get the current measurement and integrates over time to get a precise measurement value.
A 5 to 600 milliohm sense resistor is connected to RSHP and RSHN in a typical application schematic. The maximum input voltage at either RSHP or RSHN is $+/-150 \mathrm{mV}$. The sense resistor should be properly sized to accommodate the lowest and highest expected charge and discharge currents, including suspend and/ or standby currents.
Circuit traces from the sense resistor should be as short as practical without significant crossovers or feedthroughs. Failure to use a single ground reference point at the negative side of the sense resistor can significantly degrade current measurement accuracy.

The EEPROM value, NullCurr, represents the zero zone current of the battery. This is provided as a calibration guardband for reading zero current. Currents below the +/- NullCurr (in mA) limit are read as zero and are not included in the capacity algorithm calculations. A typical value for NullCurr is 3 mA , so currents between -3 mA and +3 mA will be reported as zero and not included in the capacity calculations.

The equation for current measurement resolution and sense resistor selection is shown in the following equation.

## EQUATION 2-1:

$9.15 \mathrm{mV} /$ RSENSE (milliohms) $=$ Current LSB
(Minimum current measurement if $>$ NullCurr)
Current LSB x 16384 = Maximum Current
Measurement Possible

In-circuit calibration of the current is done using the SMBus interface at time of manufacture to obtain absolute accuracy. The current measurement equation is:

## EQUATION 2-2:

$$
\mathrm{I}(\mathrm{ma})=\left(\mathrm{I} \_\mathrm{A} / \mathrm{D}-\mathrm{COCurr}-\mathbf{C O D}\right) * \text { CFCurr/16384 }
$$

where:
I_A/D is the internal measurement

COCurr is the "Correction Offset for Current" which compensates for any offset error in current measurement stored in EEPROM.
CFCurr is the "Correction Factor for Current", which compensates for any variances in the actual sense resistance over varying currents stored in EEPROM.
Figure 2-1 shows the relationship of the COCurr and CFCurr values.

FIGURE 2-1: COCurr AND CFCurr VALUE RELATIONSHIP


### 2.3 Auto-Offset Compensation

Accuracy drift is prevented using an automatic auto-zero self-calibration method, which 're-zeroes' the current measurement circuit every AOMInt * 0.5 seconds when enabled. This feature can correct for drift in temperature during operation. The auto-offset compensation circuit works internally by disconnecting the RSHP and RSHN inputs and internally shorting these inputs to measure the zero input offset. The EEPROM and calibration value, COD, is the true zero offset value of the particular module.

### 2.4 Voltage Measurements

The A/D input channel for pack voltage measurements is the $\mathrm{VC}(1)$ pin. Measurements are taken each measurement period when the $A / D$ is active. The maximum voltage at the $\mathrm{VC}(1)$ input pin is 19 V absolute, but voltages above 18 V are not suggested. The pack voltage is measured with an integration method to reduce any sudden spikes or fluctuations. The A/D uses an 11-bit Resolution mode for these measurements.
The pack voltage input is read twice per measurement period in Run mode. Voltage readings occur less frequently in Sample mode, where A/D measurements are not activated every measurement period, depending on the configuration of SampleLimit and NSample values. (See Section 3.0 "Operational Modes" for additional information.)

### 2.4.1 IMPEDANCE COMPENSATION

Since accurate measurement of pack voltage is critical to performance, the voltage measurements can be compensated for any impedance in the power path that might affect the voltage measurements.
The EEPROM value, PackResistance, is used to compensate for additional resistance that should be removed.
The equation for the compensation value (in ohms) is:

## EQUATION 2-3:

PackResistance $=$ Trace Resistance * 65535
(This is a 2-byte value, so the largest value is 1 ohm.)

This requires modification of overall voltage SBData function to compensate for pack resistance and shunt resistance of current sense resistor. Thus, the previous voltage equation is modified to:

EQUATION 2-4:
SBData Voltage Value $=\mathrm{VC}(1)+$ Measured Current (mA) * PackResistance/65535

The voltage measurement equation is:
EQUATION 2-5:
V (mV) = (V_A/D - COVPack) x CFVPack/2048 where:

V_A/D is the internal measurement output

COVPack is the "Correction Offset for Pack Voltage" which compensates for any offset error in voltage measurement. (Since the offset of the A/D is less than the voltage measurement resolution of $+/-16.5 \mathrm{mV}$, the COVPack value is typically zero.)

FIGURE 2-2: PACK RESISTANCE VALUE COMPENSATIONS


CFVPack is the "Correction Factor for Pack Voltage" which compensates for any variance in the actual $A / D$ response versus an ideal $A / D$ response over varying voltage inputs.

The COVPack and CFVPack are calibration constants that are stored in EEPROM.
Figure 2-3 shows the relationship of the COVPack and CFVPack values.

FIGURE 2-3: COVPack AND CFVPack VALUE RELATIONSHIP


In-circuit calibration of the voltage is done at the time of manufacture to obtain absolute accuracy in addition to high resolution. Individual cell voltage measurements can be accurate to within $\pm 20 \mathrm{mV}$.

### 2.5 Temperature Measurements

The A/D receives input from the internal temperature sensor to measure the temperature. Optionally, an external thermistor can be connected to the VNTC pin which is also monitored by the A/D converter. An output reference voltage for use with an external thermistor is provided on the Vreft pin. The A/D uses an 11-bit Resolution mode for the temperature measurements.
A standard 10 kOhms at $25^{\circ} \mathrm{C}$ Negative-TemperatureCoefficient (NTC) device of the 103ETB type is suggested for the optional external thermistor. One leg of the NTC should be connected to the Vreft pin and the other to both the VNTC pin and a 3.65 kOhms resistor to analog ground (VSSA). The resistor forms the lower leg of a voltage divider circuit. To maintain high accuracy in temperature measurements, a $1 \%$ resistor should be used.
A look-up table is used to convert the voltage measurement seen at the VNTC pin to a temperature value. The external thermistor should be placed as close as possible to the battery cells and should be isolated from any other sources of heat that may affect its operation.
Calibration of the temperature measurements involves a correction factor and an offset exactly like the current and voltage measurements. The internal temperature measurement makes use of correction factor CFTempl and offset COTempl, while the VNTC and VREFT pins for the optional external thermistor make use of correction factor CFTempE and offset COTempE.

### 3.0 OPERATIONAL MODES

The PS501-0901 operates on a continuous cycle. The frequency of the cycles depends on the power mode selected. There are four power modes: Run, Sample, Sleep and Shelf-Sleep. Each mode has specific entry and exit conditions as listed below.

### 3.1 Run Mode

Whether the PS501-0901 is in Run mode or Sample mode depends on the magnitude of the current. The Run and Sample mode entry-exit threshold is calculated using the EEPROM parameter, SampleLimit.

SampleLimit is a programmable EEPROM value and CFCurr is an EEPROM value set by calibration.

Entry to Run mode occurs when the current is more than +/- SampleLimit mA for two consecutive measurements. Run mode may only be exited to Sample mode, not to Sleep mode, when Sample mode is enabled. Exit from Run mode to Sample mode occurs when the converted measured current is less than the +/- SampleLimit mA threshold for two consecutive measurements.

Run mode is the highest power consuming mode. During Run mode, all measurements and calculations occur once per measurement period. Current, voltage and temperature measurements are each typically made sequentially during every measurement period.

### 3.2 Sample Mode

Entry to Sample mode occurs when the measured current is less than +/- SampleLimit (EE parameter) two consecutive measurements. Sample mode may be exited to either Run mode or Sleep mode.
While in Sample mode, measurements of voltage, current and temperature occur only once per NSample counts of measurement periods, where NSample is a programmable EEPROM value. Calculations of State-Of-Charge, SMBus requests, etc. still continue at the normal Run mode rate, but measurements only occur once every measurement period x NSample. The minimum value for NSample is two.

The purpose of Sample mode is to reduce power consumption during periods of inactivity (low rate charge or discharge). Since the analog-to-digital converter is not active, except every NSample count of measurement periods, the overall power consumption is significantly reduced.

## EXAMPLE 3-1: CONFIGURATION

Measurement period is 500 ms
SampleLimit is set to 20
NSample is set to 16
Result:
Run/Sample Mode Entry-Exit Threshold $=20 \mathrm{~mA}$
During Sample mode, measurements will occur every:
16 Measurement Periods of $500 \mathrm{~ms}=$ Every 8 Seconds

### 3.3 Low-Voltage Sleep Mode

Entry to Sleep mode can only occur when the measured pack voltage at the $\mathrm{VC}(1)$ input is below a preset limit, set by the EEPROM value SleepVPack (in mV ). Sleep mode may be exited to Run mode, but only when one of the wake-up conditions is satisfied.
While in Sleep mode, no measurements occur and no calculations are made. The fuel gauge display is not operational, no SMBus communications are recognized and only a wake-up condition will permit an exit from Sleep mode. Sleep mode is one of the lowest power consuming modes and is used to conserve battery energy following a complete discharge.

There are two levels of Low-Voltage Sleep mode that can be used, each with a different wake-up criteria. Default Low-Power mode will use $25 \mu \mathrm{~A}$ typical and will wake-up when the voltage exceeds the WakeUp voltage level. By setting bit 1 of the WakeUp register to ' 1 ', the Ultra Low-Power mode can be used. This will be entered by low voltage, but wake-up occurs by pulling the SMBus lines high. Ultra Low-Power mode uses less than $1 \mu \mathrm{~A}$.

### 3.4 Shelf-Sleep Mode

Shelf-Sleep mode is used to put the PS501-0901 into Low-Power mode, regardless of voltage level, for long term storage of battery packs. It is entered by an SMBus command. It is exited by the conditions selected in the WakeUp register. These can be voltage, current, GPIO or SMBus activity. If any of these four are selected for wake-up, the Shelf-Sleep mode will be Low-Power mode and will draw $25 \mu \mathrm{~A}$ typical. If none of these options are selected and bit 3 of the WakeUp register is set, the Shelf-Sleep mode will be Ultra LowPower mode, which will draw less than $1 \mu \mathrm{~A}$ and wake-up will be by pulling SMBus high.

TABLE 3-1: WakeUp EEPROM VALUE

| Bit | Name | Function |
| :---: | :---: | :--- |
| 7 | WakelO | Wake-up from I/O Activity |
| 6 | WakeBus | Wake-up from SMBus Activity |
| 5 | WakeCurr | Wake-up from Current |
| 4 | WakeVolt | Wake-up from Voltage |
| 3 | Enable Shelf-Sleep | Use Ultra Low-Power mode for Shelf-Sleep mode. All other bits must be zero. |
| 1 | LV Sleep Mode | Use Ultra Low-Power mode as Low-Voltage Sleep mode |
| 0 | Zero Remcap | Set Remcap to zero when entering Low-Voltage Sleep mode |

TABLE 3-2: WakeLevels EEPROM VALUE

| WakeUp Voltage (2:0) | Voltage | Purpose |
| :---: | :---: | :---: |
| 000 | 6.4 V | 2 cells Li lon |
| 001 | 6.66 V | 6 cells NiMH |
| 010 | 8.88 V | 8 cells NiMH |
| 011 | 9.6 V | 3 cells Li lon |
| 100 | 9.99 V | 9 cells NiMH |
| 101 | 11.1 V | 10 cells NiMH |
| 110 | 12.8 V | 4 cells Li lon |
| 111 | 13.3 V | 12 cells NiMH |
| WakeUp Current (7:3) | Voltage | Purpose |
| 00000 | Minimum | $\mu \mathrm{V}$ across Sense Resistor |
| 11000 | Typical Recommended | $\mu \mathrm{V}$ across Sense Resistor |
| 11111 | Maximum | $\mu \mathrm{V}$ across Sense Resistor |

## TABLE 3-3: POWER MODE SUMMARY

| Mode | Entry | Exit | Notes |
| :--- | :--- | :--- | :--- |
| Run | Measured current > preset threshold <br> (set by SampleLimit) | Measured current < preset threshold <br> (set by SampleLimit) | Highest power consumption <br> and accuracy for rapidly <br> changing current. |
| Sample | Measured current < preset threshold <br> (set by SampleLimit) | Measured current > preset threshold <br> (set by SampleLimit) | Saves power for low, steady <br> current consumption. Not as <br> many measurements <br> needed. Measurements <br> made every NSample <br> periods. |
| Sleep | VC(1) < SleepVPack and in <br> Sample mode | WakeUp voltage level exceeded <br> (Low-Power mode) or SMBus <br> pulled high (Ultra Low-Power <br> mode) | No measurements made. |

### 4.0 CAPACITY MONITORING

The PS501-0901 internal CPU uses the voltage, current and temperature data from the A/D converter, along with parameters and cell models to determine the state of the battery and to process the SBData function instruction set.

By integrating measured current, monitoring voltages and temperature, adjusting for self-discharge and checking for End-Of-Charge and End-Of-Discharge conditions, the PS501-0901 creates an accurate fuel gauge under all battery conditions.

### 4.1 Capacity Calculations

The PS501-0901 calculates State-Of-Charge and fuel gauging functions using a 'coulomb counting' method, with additional inputs from battery voltage and temperature measurements. By continuously and accurately measuring all the current into and out of the battery cells, along with accurate three-dimensional cell models, the PS501-0901 is able to provide accurate predictions of SOC and run time.
The capacity calculations consider two separate states: charge acceptance or Capacity Increasing (CI) and discharge or Capacity Decreasing (CD). The CI state only occurs when a charge current larger than EEPROM NullCurr value is measured. Otherwise, while at rest and/or while being discharged, the state is CD. Conditions must persist for at least NChangeState measurement periods for a valid state change between $C D$ and Cl . A minimum value of 2 is suggested for NChangeState.
Regardless of the Cl or CD state, self-discharge is also calculated and subtracted from the integrated capacity values. Even when charging, there is still a self-discharge occurring in the battery.
To compensate for known system errors in the capacity calculations, a separate error term is also continuously calculated. This term is the basis for the SBData value of MaxError. Two error values are located in EEPROM. The CurrError value is the inherent error in current measurements and should be set based on the selection of a sense resistor and calibration results. The SelfDischrgErr value is the error in the parameter tables for self-discharge and depends on the accuracy of the cell chemistry model for self-discharge.
Since the PS501-0901 electronics also drain current from the battery system, another EEPROM value allows even this minor drain to be included in the capacity calculations. The PwrConsumption value represents the drain of the IC and associated circuitry, including additional safety monitoring electronics, if present. A typical value of 77 represents the module's nominal power consumption, including the PS501-0901 typical consumption.

The total capacity added or subtracted from the battery (change in charge) per measurement period is expressed by the following formula:

## EQUATION 4-1:

$\Delta$ Charge $=\Sigma \mathrm{i} \Delta \mathrm{t}$ (the current integrated over time)

- CurrError (Current Measurement Error)
- PwrConsumption * $\Delta t$ (PS501-0901 IDD)
- \% of Self-Discharge * FCC
- SelfDischrgErr (Self-Discharge Error)

The error terms are always subtracted, even though they are +/- errors, so that the fuel gauge value will never be overestimated. Current draw of the PS501-0901 and the self-discharge terms are also always subtracted. The SBData value MaxError is the total accumulated error as the gas gauge is running.
The battery current will be precisely measured and integrated in order to calculate total charge removed from or added to the battery. Based on look-up table values, the capacity is adjusted with self-discharge relative to current, temperature and SOC.

### 4.2 Discharge Termination

Discharge termination is determined based on the End-Of-Discharge (EOD) voltage point. The voltage level at which this point occurs can be chosen to be constant, or to change, depending on the temperature and discharge rate, since these factors affect the voltage curve and total capacity of the battery. The EOD voltage parameter table predicts the voltage point at which this EOD will be reached, based on discharge rate and temperature.
The PS501-0901 will monitor temperature and discharge rate continuously and update the VEODx in real time. When the voltage measured on the pack is below EOD voltage for the duration of EODRecheck $x$ periods ( 500 ms ), a valid EOD has occurred.

When a valid EOD has been reached, the TERMINATE_DISCHARGE_ALARM bit (bit 11) in BatteryStatus will be set. This will cause an AlarmWarning condition with this bit set.
Additionally, the REMAINING_TIME_ALARM and/or REMAINING_CAPACITY_ALARM bits can be set first to give a user defined early warning prior to the TERMINATE_DISCHARGE_ALARM.
The REMAINING_TIME_ALARM will trigger in BatteryStatus when the remaining time calculation falls below a threshold set by the SMBus command. The REMAINING_CAPACITY_ALARM will be set in BatteryStatus when the capacity falls below a threshold set by the SMBus command. Use an SMBus write command to RemainingTimeAlarm (command code $0 \times 02$ ) or RemainingCapacityAlarm (command code $0 \times 01$ ) to set these values.

### 4.3 Capacity Relearn at Discharge Termination

To maintain accurate capacity prediction ability, the FullCapacity value is relearned on each discharge, which has reached a valid EOD after a previous valid fully charged condition (EOC). If a partial charge occurs before reaching a valid EOD, then no relearn will occur. If the discharge rate at EOD is greater than the ' C -rate' adjusted value in RelearnCurrLim, then no relearn will occur.

When a valid EOD has been reached, then the error calculations represented by the SBData value of MaxError will be cleared to zero. If appropriate, the relearned value of FullCapacity (and FullChargeCapacity) will also be updated at this time.

### 4.4 Discharge Termination Voltage Look-up Table

### 4.4.1 NEAR EMPTY SHUTDOWN POINT

As the graph in Table 4-1 shows, available capacity in the battery varies with temperature and discharge rate. Since the remaining capacity will vary, the save to disk point of a PC will also vary with temperature and discharge rate.
Knowing the discharge rate that occurs in the system during the shutdown process and knowing the temperature can pinpoint the exact shutdown point that will always leave the perfect shutdown capacity. The PS501-0901 uses this information to tailor the gas gauge to the system and the remaining capacity and RSOC fuel gauge function will always go to zero at the efficient shutdown point. The table will use the voltage points at which this happens as the error correction and FullCapacity relearn point. This will ensure a relearn point before shutdown occurs and will correct any error in remaining capacity, also to ensure proper shutdown reserve energy.
The shutdown point has to equal the capacity required to shut down the system under the conditions of the shutdown. That is, looking at the curve that represents the actual discharge C-rate that occurs during the system shutdown function, we must stop discharge and initiate shutdown when the system has used capacity equal to that point on the shutdown C -rate curve. Therefore, no matter what the C-rate is when the shutdown point is reached, the system will automatically switch to the C-rate curve that represents the actual current draw of the shutdown function. It doesn't matter if the system is in high discharge, or low discharge, it will be in "shutdown" discharge conditions when shutdown begins and there must be enough capacity left. An example is a computer's save to disk function.

Table 4-1 shows that the system will always shut down at the same capacity point regardless of C-rate conditions (since the C-rate of the shutdown procedure is a constant). Thus, we can automatically have an RSOC that is compensated for C-rate; it will go to zero when the capacity used is equal to the point at which shutdown occurs.
Ignoring the effects of temperature, we could mark the capacity used up to the shutdown point of the shutdown curve. All of the shutdown voltage points would then represent the same capacity and RSOC would always become zero at this capacity; FCC would always equal this capacity plus the residual capacity of the shutdown curve.
To compensate for temperature, we can look at the series of curves that represent the shutdown C-rate at different temperatures. The PS501-0901 implementation is to measure the temperature and choose a scaled RSOC value that will go to zero at the shutdown point at this temperature, assuming the temperature does not change. If it does change, then an adjustment to RSOC will be needed to make it go to zero at the shutdown point.
Taking temperature into consideration, the amount of capacity that can be used before shutdown is a constant as C-rate changes, but not constant as temperature changes. Thus, in the Look-up Table (LUT), the individual temperature columns will have voltage points that all represent the same capacity used, but the rows across temperature points (C-rate rows) will represent the different capacity used.
To compensate RSOC and RM, interpolation will be used and the compensation adjustment can happen in real time to avoid sudden drops or jumps. Every time the temperature decreases by one degree, a new interpolated value will be subtracted from RSOC and RM. Every time the temperature increases by one degree, RSOC and RM will be held constant until the discharged capacity equals the interpolated value that should have been added to RSOC and RM (to avoid capacity increases during discharge). With this interpolation happening in real time, there will be no big jumps or extended flat periods as we cross over boundaries in the LUT. This compensation will not begin until after the fully charged status is reset, allowing RSOC to be $100 \%$ always when the battery is full.

### 4.5 Age Compensation

The voltage EOD points will be compensated due to the age of the cells. A linear factor, AgeFactor, will be applied to the voltage points as a function of CycleCount. The voltage levels will decrease as the battery pack ages to model the flattening of the voltage vs. capacity curve that naturally happens to battery cells.

## PS501-0901

TABLE 4-1: V_EOD LOOK-UP TABLE

| $<\mathbf{0}^{\circ}$ | $<4^{\circ}$ | $<\mathbf{1 0}^{\circ}$ | $<\mathbf{1 7}^{\circ}$ | $<\mathbf{2 4 ^ { \circ }}$ | $<40^{\circ}$ | $<44^{\circ}$ | $>44^{\circ}$ |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $<0.2 \mathrm{C}$ | V 1 | V 2 | V 3 | - |  |  |  |  |
| $<0.5 \mathrm{C}$ |  |  |  |  |  |  |  |  |
| $<0.8 \mathrm{C}$ |  |  |  |  |  |  |  |  |
| $<1.1 \mathrm{C}$ |  |  |  |  |  |  |  |  |
| $<1.4 \mathrm{C}$ |  |  |  |  |  |  |  |  |
| $<1.7 \mathrm{C}$ |  |  |  |  |  |  |  |  |
| $<2.0 \mathrm{C}$ |  |  |  |  |  |  |  |  |
| $<2.0 \mathrm{C}$ |  |  |  |  | - | V 62 | V 63 | V 64 |
| Capacity | $15 \%$ | $13 \%$ | $11 \%$ | $9 \%$ | $7 \%$ | $5 \%$ | $3 \%$ | $1 \%$ |

The above table is an example of the various voltage values that will signal the shutdown points as a function of temperature and discharge rate. Also shown is the amount of capacity left after shutdown that will compensate RSOC.

Table 4-2 shows the actual names of the values in the EEPROM.

TABLE 4-2: VALUE NAMES IN THE EEPROM

|  | TEOD(1) | TEOD(2) | TEOD(3) | TEOD(4) | TEOD(5) | TEOD(6) | TEOD(7) | TEOD(8) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| CEOD(1) | VEOD1(1) | VEOD1(2) | VEOD1(3) | VEOD1(4) | VEOD1(5) | VEOD1(6) | VEOD1(7) | VEOD1(8) |
| CEOD(2) | VEOD2(1) | VEOD2(2) | VEOD2(3) | VEOD2(4) | VEOD2(5) | VEOD2(6) | VEOD2(7) | VEOD2(8) |
| CEOD(3) | VEOD3(1) | VEOD3(2) | VEOD3(3) | VEOD3(4) | VEOD3(5) | VEOD3(6) | VEOD3(7) | VEOD3(8) |
| CEOD(4) | VEOD4(1) | VEOD4(2) | VEOD4(3) | VEOD4(4) | VEOD4(5) | VEOD4(6) | VEOD4(7) | VEOD4(8) |
| CEOD(5) | VEOD5(1) | VEOD5(2) | VEOD5(3) | VEOD5(4) | VEOD5(5) | VEOD5(6) | VEOD5(7) | VEOD5(8) |
| CEOD(6) | VEOD6(1) | VEOD6(2) | VEOD6(3) | VEOD6(4) | VEOD6(5) | VEOD6(6) | VEOD6(7) | VEOD6(8) |
| CEOD(7) | VEOD7(1) | VEOD7(2) | VEOD7(3) | VEOD7(4) | VEOD7(5) | VEOD7(6) | VEOD7(7) | VEOD7(8) |
| CEOD(8) | VEOD8(1) | VEOD8(2) | VEOD8(3) | VEOD8(4) | VEOD8(5) | VEOD8(6) | VEOD8(7) | VEOD8(8) |
|  | FCCP(1) | FCCP(2) | FCCP(3) | FCCP(4) | FCCP(5) | FCCP(6) | FCCP(7) | FCCP(8) |

## TABLE 4-3: VALUE DEFINITIONS IN THE EEPROM

| TEOD 8 coded bytes | typ: 50, 62, 75, 94, 112, 150, 162 | Range: 1-255 per byte |
| :---: | :---: | :---: |
| EOD temperature boundaries, 8 increasing values of temperature coded as TEODx = (Tcelsius * $10+200$ )/4 |  |  |
| CEOD 8 coded bytes | typ: 16, 24, 32, 43, 53, 64, 72 | Range: 1-255 |
| EOC C-rate boundaries, 8 increasing values of C-rates coded: <br> CEODx = C-rate * (256/28/RF), where RF is the Rate Factor (RFACTOR) EEPROM parameter. <br> For $\mathrm{RF}=7$, CEODx $=$ C-rate * 64 . Thus, a value of 32 is one-half C , etc. |  |  |
| FCCP coded \% | typ: 40, 35, 30, 25, 20, 15, 10, 5 | Range: 1-255 |
| Unusable residual capacity before save to disk, corresponding to temperature, $255=100 \%$ |  |  |
| VEOD coded | typ: 75 | Range: 1-255 |
| End-Of-Discharge voltage, voltage $=(\mathrm{VEOD} * 2+700)^{*}(\#$ series cells). Pack voltage at which shutdown is signaled. |  |  |

### 5.0 CHARGE CONTROL

An SBS configuration normally allows the Smart Battery to broadcast the ChargingVoltage and ChargingCurrent values to the Smart Battery Charger (SMBus address 12 hex) to 'control' when to start charge, stop charge and when to signal a valid 'fully charged' condition. AlarmWarnings are also sent from the Smart Battery (SMBus address 16 hex) to the Smart Battery Charger.
Alternately, the SMBus host, or a "Level 3" Smart Battery Charger, may simply read the SBData values for ChargingVoltage and ChargingCurrent from the Smart Battery directly. The host or "Level 3" Smart Battery Charger is also required to read the SBData value of BatteryStatus to obtain the appropriate alarm and status bit flags. When used in this configuration, the ChargingCurrent and ChargingVoltage broadcasts can be disabled from the Smart Battery by setting the CHARGER_MODE (bit 14) in the BatteryMode register. The PS501-0901 ICs support all of these functions. (Please refer to the SBS Smart Battery Charger specification for a definition of the "Level 3" Smart Battery Charger.)
The ChargingCurrent and ChargingVoltage registers contain the maximum charging parameters desired by the particular chemistry, configuration and environmental conditions. The environmental conditions include the measured temperature and the measured cell or pack voltages.
For Ni-based systems, ChargingVoltage should be set to 65535 . This value indicates that the Smart Battery Charger should operate as a current source outside its maximum regulated voltage range.
The ChargingCurrent value is set to a maximum using the ChrgCurr value from the EEPROM and to a minimum using the ChrgCurrOff value. The value of ChargingCurrent may change when the temperature limits are exceeded during charge. When a valid End-Of-Charge (EOC) condition is detected and a fully charged state is reached, the ChargingCurrent value is set to the ChrgCurrOff value.
When ChargingCurrent is set to the ChrgCurrOff value, no broadcasts of either ChargingCurrent or ChargingVoltage will occur unless a charge current greater than NullCurr is detected by the $A / D$ measurements. Temperature limits are set using the ChrgMaxTemp, DischrgMaxTemp and ChrgMinTemp values from EEPROM. These values represent the temperature limits within which ChargingCurrent will be set to ChrgCurr. Temperatures outside these limits will cause ChargingCurrent to be set to ChrgCurrOff.
If ChargingCurrent is set to ChrgCurrOff and the measured temperature is greater than DischrgMaxTemp and less than ChrgMaxTemp and a charge current is measured which is significantly larger than the

ChrgCurrOff value, then ChargingCurrent will be set to ChrgCurr unless a fully charged condition has already been reached.

If the CHARGER_MODE bit in the BatteryMode register is cleared (enabling broadcasts of ChargingCurrent and ChargingVoltage), then these broadcasts will occur every NChrgBroadcast measurement cycle.
The Smart Battery Data and Smart Battery Charger specifications require that ChargingCurrent and ChargingVoltage broadcasts occur no faster than once per 5 seconds and no slower than once per 60 seconds when charging is occurring or desired. This requires that the NChrgBroadcast value must be set between 10 and 120. The SMBus specification also requires that no broadcasts occur during the first 10 seconds after SMBus initialization.

## EXAMPLE 5-1: CHARGE CONTROL

Measurement cycle is 500 msec
NChrgBroadcast $=100$ decimal
ChrgCurr = 2500 decimal
ChrgCurrOff $=10$ decimal
ChrgMaxTemp = 162 decimal
DischrgMaxTemp = 137 decimal
ChrgMinTemp $=50$ decimal
Results:
ChargingCurrent and ChargingVoltage broadcasts:
100 cycles of $500 \mathrm{msec}=$ every 50 seconds
Broadcast delay after SMBus initialization:
10 seconds
ChargingCurrent if Temperature $>45^{\circ} \mathrm{C}: 10 \mathrm{~mA}$
ChargingCurrent if Temperature $<0^{\circ} \mathrm{C}: 10 \mathrm{~mA}$ ChargingCurrent if Temperature $<35^{\circ} \mathrm{C}$ and $>0^{\circ} \mathrm{C}: 2500 \mathrm{~mA}$

### 5.1 Full Charge Detection Methods

The PS501-0901 monitors pack voltage and temperature to determine the battery full End-Of-Charge (EOC) condition. There are five possible fully charged EOC conditions that are monitored according to control parameters. These methods are designed to detect a fully charged battery over a range of operating temperatures and charge rates. Figure 5-1 gives a summary of the EOC algorithm. ConfigEOC is used to choose which EOC methods will be monitored. A detailed parameter explanation for all of the full charge detection parameters is in Section 8.0 "Parameter Setup".

FIGURE 5-1: EOC OVERVIEW FLOW CHART


When a valid, fully charged EOC condition is detected, regardless of the detection method, the following actions occur:

- The FULLY_CHARGED status bit (bit 5) in the SBData value of BatteryStatus is set to ' 1 ' to indicate a full condition. (This will remain set until RelativeStateOfCharge drops below the ClrFullyChrg value in EEPROM.)
- RelativeStateOfCharge is set to $100 \%$ except when EOC is triggered by dT/dt and it is set to 95\%.
- ChargingCurrent is set to ChrgCurrOff value.
- SBData value for MaxError is cleared to zero percent (0\%).
- The TERMINATE_CHARGE_ALARM bit (bit 14) is set in BatteryStatus and an AlarmWarning broadcast is sent to the SMBus host and Smart Battery Charger addresses.
- The OverChrg value is incremented for any charge received above 100\% after a valid fully charged EOC condition.
- Control flags for internal operations are set to indicate a valid full charge condition was achieved.
- Other BatteryStatus or AlarmWarning flag bits may also be set depending on the conditions causing the EOC.
- The charge timer, EOCTimer, is exceeded
- Cell voltage is higher than TCAVolt


### 5.1.1 TEMPERATURE EOC

The rate of rise of the battery temperature is the first and primary full charge detection mechanism. This is a well known method used for Nickel-based chemistries and is commonly referenced as the "dT/dt" method (delta-Temperature over delta-time). The rate of temperature rise over a finite period of time is continually monitored. A rapid increase at an inflection point is detected as End-Of-Charge point. This inflection point is usually seen just before a fully charged state, so the resulting State-Of-Charge (SOC) Reset may be slightly less than $100 \%$. Typically, a dT/dt rate of $1^{\circ} \mathrm{C}$ per minute can accurately detect the $95 \%$ full point when used with charging rates near the $1^{\circ} \mathrm{C}$ or 1 hour rate. Although this method is active during any charge rate, it typically only occurs for charge rates of $0.8^{\circ} \mathrm{C}$ or higher. Figure 5-2 gives an overview of the temperature EOC algorithm.

FIGURE 5-2: dT/dt FLOW CHART


All of the control parameters regarding a temperature (dT/dt) EOC are available for customizing:

## TABLE 5-1: dT/dt CONTROL

PARAMETERS

| Parameter | Description |
| :---: | :--- |
| EOCdTSOC | SOC Reset value when a dT/dt EOC <br> condition occurs |
| EOCdTTemp | Minimum temperature change <br> between two samples to cause EOC |

### 5.1.2 VOLTAGE DROP EOC

The second full charge detection mechanism looks for a negative voltage drop after reaching a peak. This is also an established method for Nickel-based chemistries and is termed the "-dV" method (negative delta-V). Just at the point of full charge, the voltage profile of the battery cells will start to drop from a peak value. This drop, if measured while the current remains stable, indicates a $100 \%$ full charge condition. Generally, a -10 mV per cell drop occurs. Charge rates above $0.5^{\circ} \mathrm{C}$ are typically required to cause this method to be observed. This voltage drop method looks for a total pack voltage drop. If the charge current is stable and the voltage drops the programmed amount, a full charge EOC is signaled. Figure 5-3 gives an overview of the voltage drop EOC algorithm.

FIGURE 5-3: -dV FLOW CHART


All of the control parameters regarding a voltage drop (-dV) EOC are available for customizing:

## TABLE 5-2: -dV CONTROL PARAMETERS

| Parameter | Description |
| :--- | :--- |
| EOCdVCurr | Minimum charge current required to <br> enable -dV EOC |
| EOCdVDelay | Delay prior to -dV samples |
| EOCdVVoltDrop | Minimum voltage drop required to <br> trigger EOC |

### 5.1.3 FIXED OVERCHARGE EOC

When charging at low rates, neither of the previously mentioned full charge EOC conditions may occur. Since there are no signals from the battery temperature, voltage or current to aid in determining a full charge, a simple 'count' mechanism is used. By simply integrating the total charge that has entered the battery cells, a fixed amount of overcharge can signal a full charge EOC condition. For Nickel-based chemistries, this varies between 20 and $50 \%$ of their rated capacity. Typically, at charge rates less than $0.4^{\circ} \mathrm{C}$, neither the $d T / d t$ or -dV EOC methods will occur. An accumulated charge of 120 to $150 \%$ of the last full charge capacity is a good indicator of full charge. This fixed amount of overcharge method is reliable for low rate charging, or long term charging, since it effectively serves as a charge timer as well.

### 5.1.4 TIMER EOC

The overcharging of Nickel batteries, even by trickle charging, causes deterioration in the characteristics of the batteries. To prevent overcharging, an EOC timer can be used to discontinue charging when the charge time has exceeded EOCTimeout.

### 5.2 Temperature Algorithms

The PS501-0901 SMBus Smart Battery IC provides multiple temperature alarm set points and charging conditions. The following EEPROM parameters control how the temperature alarms and charging conditions operate.
HighTempAI: When the measured temperature is greater than HighTempAI, the OVER_TEMP_ALARM is set. If the battery is charging, then the TERMINATE_CHARGE_ALARM is also set.
ChrgMinTemp, DischrgMaxTemp, ChrgMaxTemp: If the measured temperature is less than ChrgMinTemp, the ChargingCurrent is set to ChrgCurrOff and the ChargingVoltage is set to ChrgVolt to communicate to the charger that the non-charging state of current and voltage should be given. When measured temperature is greater than ChrgMaxTemp and the system is charging, or greater than DischrgMaxTemp and the system is discharging, then ChargingCurrent is set to ChrgCurrOff and the ChargingVoltage is set to ChrgVoltOff also. Otherwise, ChargingCurrent = ChrgCurr and ChargingVoltage $=$ ChrgVolt.

## PS501-0901

### 6.0 GPIO CONFIGURATION

GPIOs can be set up to act as inputs or outputs that are based on conditions involving SBData parameters, or GPIO levels, compared to constants. This powerful programming model allows for customizing GPIO to set on any possible fuel gauge conditions and reset on any other possible fuel gauge conditions in any groupings.

TABLE 6-1: GPIO CONFIGURATIONS

| Name | Length | Definition |
| :--- | :---: | :--- |
| GPIOSTATE | 2 | Initialized default state (positive logic) |
| GPIODIRECTION | 2 | Initialized direction: <br> $1=$ input <br> $0=$ output |
| GPIOCONFIG | 2 | GPIO configuration <br> Bit 8: <br> $1=$ Pull-ups/downs disabled <br> $0=$ Pull-downs enabled <br> Bits 7-0: |
|  |  | If input: <br> $1=$ Pulled down <br> $0=$ Pulled up <br> If output: <br> $1=$ LED drive (GPIO0-7 only) <br> $0=$ Standard logic |
| GPIOPOLARITY |  |  |
|  |  | "Polarity" mask applied to invert positive logic |

GPIOs configured above as standard logic output can be programmed to activate or reset in response to any group of fuel gauge conditions. Each "condition" is defined by 4 bytes.

TABLE 6-2: GPIO CONDITIONS

| Byte | Condition | Definition |
| :---: | :---: | :---: |
| Byte 1 | Flags | bit 7: ' 1 ' signifies last condition in group <br> bit 4: Combination function (1: AND, $0: ~ O R$ ) <br> bit 3: Signed (' 1 ') or unsigned (' 0 ') <br> bits 2-0: Comparison function (0:>, $1:<, 2:=, 3$ : AND, 4 : NOR) |
| Byte 2 | Condition selection | x00-x3F SBData command code <br> $\times 40-$ State flags <br> $\times 41-$ GPIO flags <br> x42 - N/A <br> x43 - N/A <br> x44 - N/A <br> x45 - Misc. flags |
| Byte 3 <br> Byte 4 | Condition threshold | Constant |

Each condition in the table is processed by applying a "comparison function" to the selected data ("condition selection") and the given constant ("condition threshold"). The result of this operation ("true" or "false") from each condition in the group is combined as dictated by the "AND-OR" "combination function" bit in the flag byte. Because the "AND" function has precedence over the "OR", processing the CG can be described as OR'ing subgroups of ANDs (see Example 6-1 below).
One 8-bit timer (clocked at 500 msec ) is associated with all 16 CSF(s). The timer compared to its threshold is an implied "AND" term to the CG (i.e., if processing
of the CG to set the CSF results in "true", the timer is incremented and if timer >= threshold, the SF is set; otherwise, the SF is not set even though the GC is satisfied). If processing of the CG to set the CSF results in "false", the timer is set to zero. The timer is not allowed to increment past the threshold.
The conditions in the order they are stored in memory will build the activation equation until bit 7 of byte 1 is set, signifying the last condition of the group. At that point, the next group of conditions is the Reset equation. When the next to last condition bit is set, a new activation group begins.

## EXAMPLE 6-1: CONDITION GROUPS

## Example Condition Group:

(VPACK < 9000) .AND. (CURR > 100) .OR. (TEMP > 60) .AND. (CURR > 200)
because of precedence, the equation would be interpreted:
((VPACK < 9000).AND. $($ CURR > 100)). OR. $(($ TEMP > 60) $. A N D .(C U R R ~>~ 200)) ~$

## Example Reset Condition Group:

(VPACK > 9000) OR (CURR = 200)

TABLE 6-3: CONDITIONS FOR EXAMPLE 6-1

| Condition | Byte 1 | Byte 2 | Byte 3, 4 | Description |
| :---: | :---: | :---: | :---: | :---: |
| 1 | $\times 01$ | x42 | x0C80 | OR VPACK < 9000 |
| 2 | x10 | x0A | x0064 | AND CURR > 100 |
| 3 | x00 | x08 | x0D02 | OR TEMP > 60 ${ }^{\circ} \mathrm{C}$ (3330 degrees K * 10 ) |
| 4 | x80 | x0A | x00C8 | AND CURR > 200 (last condition bit set) |
| 1 | x00 | x42 | x0C80 | OR VPACK > 9000 |
| 2 | x82 | x0A | x00C8 | OR CURR = 200 (last condition bit set) |

## TABLE 6-4: PARAMETERS

| Name | Length | Description |
| :--- | :---: | :--- |
| SAFE_GPIO_MASK_00 | 2 | Mask applied to the CSF, if $<>0$ 0, GPIO is set |
| SAFE_GPIO_MASK_01 | 2 | Mask applied to the CSF, if $<>0$, GPIO is set |
| SAFE_GPIO_MASK_02 | 2 | Mask applied to the CSF, if $<>0$, GPIO is set |
| SAFE_GPIO_MASK_03 | 2 | Mask applied to the CSF, if $<>0$, GPIO is set |
| SAFE_GPIO_MASK_04 | 2 | Mask applied to the CSF, if $<>0$, GPIO is set |
| SAFE_GPIO_MASK_05 | 2 | Mask applied to the CSF, if $<>0$, GPIO is set |
| SAFE_GPIO_MASK_06 | 2 | Mask applied to the CSF, if $<>0$, GPIO is set |
| SAFE_GPIO_MASK_07 | 2 | Mask applied to the CSF, if $<>0$, GPIO is set |
| SAFE_GPIO_MASK_08 | 2 | Mask applied to the CSF, if $<>0$, GPIO is set |
| SAFE_GPIO_MASK_09 | 2 | Mask applied to the CSF, if $<>0$, GPIO is set |
| SAFE_GPIO_MASK_10 | 2 | Mask applied to the CSF, if $<>0$, GPIO is set |
| SAFE_GPIO_MASK_11 | 2 | Mask applied to the CSF, if $<>0$, GPIO is set |

## PS501-0901

## TABLE 6-4: PARAMETERS (CONTINUED)

| Name | Length | Description |
| :--- | :---: | :--- |
| SAFE_TIMER_LIMIT_0 | 1 | Timer threshold/limit (500 msec tics) |
| SAFE_TIMER_LIMIT_1 | 1 |  |
| SAFE_TIMER_LIMIT_2 | 1 |  |
| SAFE_TIMER_LIMIT_3 | 1 |  |
| SAFE_TIMER_LIMIT_4 | 1 |  |
| SAFE_TIMER_LIMIT_5 | 1 |  |
| SAFE_TIMER_LIMIT_6 | 1 |  |
| SAFE_TIMER_LIMIT_7 | 1 |  |
| SAFE_TIMER_LIMIT_8 | 1 |  |
| SAFE_TIMER_LIMIT_9 | 1 |  |
| SAFE_TIMER_LIMIT_10 | 1 |  |
| SAFE_TIMER_LIMIT_11 | 1 |  |
| SAFE_TIMER_LIMIT_12 | 1 |  |
| SAFE_TIMER_LIMIT_13 | 1 |  |
| SAFE_TIMER_LIMIT_14 | 1 |  |
| SAFE_TIMER_LIMIT_15 | 1 |  |
| SAFE_FLAG_COUNT | 1 | Number of CSF(s) to process, 0-16 (there must be 2 condition groups <br> (CGs) per CSF) |
| SAFE_CONDITION | 4 | Condition (start of table) |
| $\ldots$ | 4 | Condition |
| SAFE_CONDITION | 4 | Condition (end of table) |

### 6.1 LED Parameters

When configured as LED drivers, the following parameters determine the State-Of-Charge at which each LED will turn on.

## TABLE 6-5: LED PARAMETERS

| Name | Length | Definition |
| :--- | :---: | :--- |
| LED_MASK | 1 | Mask defining GPIO(s) used for LED display(s) (1 = LED). |
| LED_VALUE_0 | 1 | GPIO 0 SOC value (SOC >= LED_VALUE, LED = on). |
| LED_VALUE_1 | 1 | GPIO 1 SOC value (SOC >= LED_VALUE, LED = on). |
| LED_VALUE_2 | 1 | GPIO 2 SOC value (SOC >= LED_VALUE, LED = on). |
| LED_VALUE_3 | 1 | GPIO 3 SOC value (SOC >= LED_VALUE, LED = on). |
| LED_VALUE_4 | 1 | GPIO 4 SOC value (SOC >= LED_VALUE, LED = on). |
| LED_VALUE_5 | 1 | GPIO 5 SOC value (SOC >= LED_VALUE, LED = on). |
| LED_VALUE_6 | 1 | GPIO 6 SOC value (SOC >= LED_VALUE, LED = on). |
| LED_VALUE_7 | 1 | GPIO 7 SOC value (SOC >= LED_VALUE, LED = on). |
| LED_ICHG | 2 | Current threshold for LED display. |
| LED_DUTYCYCLE | 1 | Duty cycle of LED drivers. |
| GPIO_SWITCHMASK | 2 | Mask for switch input(s). If switch is active-high, all bits are 'o' except switch pin. If <br> switch is active-low, all bits are ‘1' except switch pin. |
| LED_DISPLAY_TIME | 1 | Number of 500 ms periods LEDs are lit after switch press. |

### 7.0 SMBus/SBData INTERFACE

The PS501-0901 uses a two-pin System Management Bus (SMBus) protocol to communicate to the host. One pin is the clock and one is the data. The SMBus port responds to all commands in the Smart Battery Data specification (SBData). To receive information about the battery, the host sends the appropriate commands to the SMBus port. Certain alarms, warnings and charging information may be sent to the host by the PS501-0901 automatically. The SMBus protocol is explained in this chapter. The SBData command set is summarized in Table 7-1.
The PS501-0901 SMBus communications port is fully compliant with the System Management Bus specification, version 1.1 and supports all previous and new requirements, including bus time-outs (both slave and master), multi-master arbitration, collision detection/ recovery and PEC (CRC-8) error checking. The SMBus port serves as a slave for both read and write functions, as well as a master for write word functions. SMBus slave protocols supported include read word, write word, read block and write block, all with or without PEC (CRC-8) error correction. Master mode supports write word protocols. The PS501-0901 meets and exceeds the Smart Battery Data specification, version 1.1/1.1a requirements. The PS501-0901 is compliant with System Management Bus specification 1.0.

The PS501-0901 fully implements the Smart Battery Data (SBData) specification v1.1. The SBData specification defines the interface and data reporting mechanism for an SBS compliant Smart Battery. It defines a consistent set of battery data to be used by a power management system to improve battery life and system run time, while providing the user with accurate information. This is accomplished by incorporating fixed, measured, calculated and predicted values, along with charging and alarm messages, with a simple communications mechanism between a host system, Smart Batteries and a Smart Charger.
The PS501-0901 provides full implementation of the SBData set with complete execution of all the data functions, including subfunctions and control bits and flags, compliance to the accuracy and granularity associated with particular data values and proper SMBus protocols and timing.

### 7.1 SBData Function Description

The subsections following Table 7-1 document the detailed operation of all of the individual SBData commands.

## TABLE 7-1: SMART BATTERY DATA FUNCTIONS

| SBData Function Name | Command Code | Access | Parameter Reference | Units |
| :---: | :---: | :---: | :---: | :---: |
| ManufacturerAccess-Write | $0 \times 00$ | R/W | PW1, PW2 | Code |
| ManufacturerAccess-Read | $0 \times 00$ | R/W | Chip version | Code |
| RemainingCapacityAlarm | $0 \times 01$ | R/W | RemCapAI | mAh or 10 mWh |
| RemainingTimeAlarm | $0 \times 02$ | R/W | RemTimeAI | Minutes |
| BatteryMode | $0 \times 03$ | R/W |  | Bit code |
| AtRate | $0 \times 04$ | Read |  | mAh or 10 mWh |
| AtRateTimeToFull | $0 \times 05$ | Read |  | Minutes |
| AtRateTimeToEmpty | $0 \times 06$ | Read |  | Minutes |
| AtRateOK | $0 \times 07$ | Read |  | Binary 0/1 (LSB) |
| Temperature | $0 \times 08$ | Read |  | $0.1^{\circ} \mathrm{K}$ |
| Voltage | $0 \times 09$ | Read |  | mV |
| Current | $0 \times 0 \mathrm{a}$ | Read |  | mA |
| AverageCurrent | $0 \times 0 \mathrm{~b}$ | Read |  | mA |
| MaxError | $0 \times 0 \mathrm{c}$ | Read |  | \% |
| RelativeStateOfCharge | $0 \times 0 \mathrm{~d}$ | Read |  | \% |
| AbsoluteStateOfCharge | $0 \times 0 \mathrm{e}$ | Read |  | \% |
| RemainingCapacity | 0xOf | Read |  | mAh or 10 mWh |
| FullChargeCapacity | $0 \times 10$ | Read |  | mAh or 10 mWh |
| RunTimeToEmpty | $0 \times 11$ | Read |  | Minutes |
| AverageTimeToEmpty | $0 \times 12$ | Read |  | Minutes |
| AverageTimeToFull | $0 \times 13$ | Read |  | Minutes |
| ChargingCurrent | $0 \times 14$ | Read | ChrgCurr or ChrgCurrOff | mA |
| ChargingVoltage | $0 \times 15$ | Read | ChrgVolt or ChrgVoltOff | mV |
| BatteryStatus | $0 \times 16$ | Read | BatStatus | Bit code |
| CycleCount | $0 \times 17$ | Read | Cycles | Integer |
| DesignCapacity | $0 \times 18$ | Read | DesignCapacity | mAh or 10 mWh |
| DesignVoltage | $0 \times 19$ | Read | DesignVPack | mV |
| SpecificationInfo | $0 \times 1 \mathrm{a}$ | Read | SBDataVersion | Coded |
| ManufactureDate | 0x1b | Read | Date | Coded |
| SerialNumber | 0x1c | Read | SerialNumber | Not specified |
| Firmwarelnfo ${ }^{(1)}$ | 0x1d | Read | FW Version and PW1, PW2 | Coded |
| ManufacturerName | $0 \times 20$ | Read | MFGName | ASCII text string |
| DeviceName | $0 \times 21$ | Read | DeviceName | ASCII text string |
| DeviceChemistry | $0 \times 22$ | Read | Chemistry | ASCII text string |
| ManufacturerData | $0 \times 23$ | Read | MFGData | HEX string |
| OptionalMfgFunction4 | $0 \times 3 \mathrm{c}$ | Read |  |  |
| OptionalMfgFunction3 | 0x3d | Read |  |  |
| OptionalMfgFunction2 | $0 \times 3 \mathrm{e}$ | Read |  |  |
| OptionalMfgFunction1 | 0x3f | Read |  |  |
| OptionalMfgFunction5 | 0x2f | Read | GPIO pin status | Bit-coded data |

Note 1: Reports internal software version when read, opens EEPROM (and selected other values) for programming when written.

### 7.1.1 ManufacturerAccess (0x00)

Reports internal software version when read, opens EEPROM for programming when written with the password.

### 7.1.2 RemainingCapacityAlarm (0x01)

Sets or reads the low capacity alarm value. Whenever the remaining capacity falls below the low capacity alarm value, the Smart Battery sends alarm warning messages to the SMBus host with the REMAINING_CAPACITY_ALARM bit set. A low capacity alarm value of ' 0 ' disables this alarm.

### 7.1.3 RemainingTimeAlarm (0x02)

Sets or reads the remaining time alarm value. Whenever the AverageTimeToEmpty falls below the remaining time value, the Smart Battery sends alarm warning messages to the SMBus host with the REMAINING_TIME_ALARM bit set. A remaining time value of ' 0 ' disables this alarm.

### 7.1.4 BatteryMode (0x03)

This function selects the various battery operational modes and reports the battery's capabilities, modes and condition.

## Bit 0: INTERNAL_CHARGE_CONTROLLER

Bit set indicates that the battery pack contains its own internal charge controller. When the bit is set, this optional function is supported and the CHARGE_CONTROLLER_ENABLED bit will be activated.

## Bit 1: PRIMARY_BATTERY_SUPPORT

Bit set indicates that the battery pack has the ability to act as either the primary or secondary battery in a system. When the bit is set, this optional function is supported and the PRIMARY_BATTERY bit will be activated.

## Bit 2-6: Reserved

## Bit 7: CONDITION_FLAG

Bit set indicates that the battery is requesting a conditioning cycle. This typically will consist of a full charge to full discharge, back to full charge of the pack. The battery will clear this flag after it detects that a conditioning cycle has been completed.

## Bit 8: CHARGE_CONTROLLER_ENABLED

Bit is set to enable the battery pack's internal charge controller. When this bit is cleared, the internal charge controller is disabled (default). This bit is active only when the INTERNAL_CHARGE_CONTROLLER bit is set.

## Bit 9: PRIMARY_BATTERY

Bit is set to enable a battery to operate as the primary battery in a system. When this bit is cleared, the battery operates in a secondary role (default). This bit is active only when the PRIMARY_BATTERY_SUPPORT bit is set.

Bit 10-13: Reserved
Bit 14: CHARGER_MODE
Enables or disables the Smart Battery's transmission of ChargingCurrent and ChargingVoltage messages to the Smart Battery Charger. When set, the Smart Battery will not transmit ChargingCurrent and ChargingVoltage values to the charger. When cleared, the Smart Battery will transmit the ChargingCurrent and ChargingVoltage values to the charger when charging is desired.
Bit 15: CAPACITY_MODE
Indicates if capacity information will be reported in $\mathrm{mA} / \mathrm{mAh}$ or $10 \mathrm{~mW} / 10 \mathrm{mWh}$. When set, the capacity information will be reported in $10 \mathrm{~mW} / 10 \mathrm{mWh}$. When cleared, the capacity information will be reported in $\mathrm{mA} / \mathrm{mAh}$.

### 7.1.5 AtRate ( $0 \times 04$ )

AtRate is a value of current or power that is used by three other functions: AtRateTimeToFull, AtRateTimeToEmpty and AtRateOK:

- AtRateTimeToFull returns the predicted time to full charge at the AtRate value of charge current.
- AtRateTimeToEmpty function returns the predicted operating time at the AtRate value of discharge current.
- AtRateOK function returns a Boolean value that predicts the battery's ability to supply the AtRate value of additional discharge current for 10 seconds.


### 7.1.6 AtRateTimeToFull (0x05)

Returns the predicted remaining time to fully charge the battery at the AtRate value (mA). The AtRateTimeToFull function is part of a two-function call set used to determine the predicted remaining charge time at the AtRate value in mA. It will be used immediately after the SMBus host sets the AtRate value.

### 7.1.7 AtRateTimeToEmpty (0x06)

Returns the predicted remaining operating time if the battery is discharged at the AtRate value. The AtRateTimeToEmpty function is part of a two-function call set used to determine the remaining operating time at the AtRate value. It will be used immediately after the SMBus host sets the AtRate value.

### 7.1.8 AtRateOK (0x07)

Returns a Boolean value that indicates whether or not the battery can deliver the AtRate value of additional energy for 10 seconds (Boolean). If the AtRate value is zero or positive, the AtRateOK function will always return true. The AtRateOK function is part of a twofunction call set used by power management systems to determine if the battery can safely supply enough energy for an additional load. It will be used immediately after the SMBus host sets the AtRate value.

### 7.1.9 Temperature (0x08)

Returns the cell pack's internal temperature in units of $0.1^{\circ} \mathrm{K}$.

### 7.1.10 Voltage (0x09)

Returns the pack voltage (mV).

### 7.1.11 Current (0x0a)

Returns the current being supplied (or accepted) through the battery's terminals (mA).

### 7.1.12 AverageCurrent (0x0b)

Returns a one-minute rolling average based on at least 60 samples of the current being supplied (or accepted) through the battery's terminals (mA).

### 7.1.13 MaxError (0x0c)

Returns the expected margin of error (\%) in the State-Of-Charge calculation. For example, when MaxError returns $10 \%$ and RelativeStateOfCharge returns 50\%, the RelativeStateOfCharge is actually between $50 \%$ and $60 \%$. The MaxError of a battery is expected to increase until the Smart Battery identifies a condition that will give it higher confidence in its own accuracy. For example, when a Smart Battery senses that it has been fully charged from a fully discharged state, it may use that information to reset or partially reset MaxError. The Smart Battery can signal when MaxError has become too high by setting the CONDITION_FLAG bit in BatteryMode.

### 7.1.14 RelativeStateOfCharge (0x0d)

Returns the predicted remaining battery capacity expressed as a percentage of FullChargeCapacity (\%).

### 7.1.15 AbsoluteStateOfCharge ( $0 \times 0 \mathrm{e}$ )

Returns the predicted remaining battery capacity expressed as a percentage of DesignCapacity (\%). Note that AbsoluteStateOfCharge can return values greater than $100 \%$.

### 7.1.16 RemainingCapacity (0x0f)

Returns the predicted remaining battery capacity. The RemainingCapacity value is expressed in either current ( mAh ) or power ( 10 mWh ), depending on the setting of the BatteryMode's CAPACITY_MODE bit.

### 7.1.17 FullChargeCapacity ( $0 \times 10$ )

Returns the predicted pack capacity when it is fully charged. It is based on either current or power, depending on the setting of the BatteryMode's CAPACITY_MODE bit.

### 7.1.18 RunTimeToEmpty ( $0 \times 11$ )

Returns the predicted remaining battery life at the present rate of discharge (minutes). The RunTimeToEmpty value is calculated based on either current or power, depending on the setting of the BatteryMode's CAPACITY_MODE bit. This is an important distinction because use of the wrong Calculation mode may result in inaccurate return values.

### 7.1.19 AverageTimeToEmpty (0x12)

Returns a one-minute rolling average of the predicted remaining battery life (minutes). The AverageTimeToEmpty value is calculated based on either current or power, depending on the setting of the BatteryMode's CAPACITY_MODE bit. This is an important distinction because use of the wrong Calculation mode may result in inaccurate return values.

### 7.1.20 AverageTimeToFull (0x13)

Returns a one-minute rolling average of the predicted remaining time until the Smart Battery reaches full charge (minutes).

### 7.1.21 ChargingCurrent ( $0 \times 14$ )

Sets the maximum charging current for the Smart Battery Charger to charge the battery. This can be written to the Smart Battery Charger from the Smart Battery or requested by the Smart Battery Charger from the battery.

### 7.1.22 ChargingVoltage ( $0 \times 15$ )

Sets the maximum charging voltage for the Smart Battery Charger to charge the battery. This can be written to the Smart Battery Charger from the Smart Battery or requested by the Smart Battery Charger from the battery.

### 7.1.23 BatteryStatus (0x16)

Returns the Smart Battery's status word (flags). Some of the BatteryStatus flags, like REMAINING_CAPACITY_ALARM and REMAINING_TIME_ALARM, are calculated based on either current or power, depending on the setting of the BatteryMode's CAPACITY_MODE bit. This is important because use of the wrong Calculation mode may result in an inaccurate alarm. The BatteryStatus function is used by the power management system to get alarm and status bits, as well as error codes, from the Smart Battery. This is basically the same information returned by the SBData AlarmWarning function, except that the AlarmWarning function sets the error code bits all high before sending the data. Also, information broadcasting is disabled in the PS501-0901.

## Battery Status Bits:

bit 15: OVER_CHARGED_ALARM
bit 14: TERMINATE_CHARGE_ALARM
bit 13: Reserved
bit 12: OVER_TEMP_ALARM
bit 11: TERMINATE_DISCHARGE_ALARM
bit 10: Reserved
bit 9: REMAINING_CAPACITY_ALARM
bit 8: REMAINING_TIME_ALARM
bit 7: INITIALIZED
bit 6: DISCHARGING
bit 5: FULLY_CHARGED
bit 4: FULLY_DISCHARGED
The host system assumes responsibility for detecting and responding to Smart Battery alarms by reading the BatteryStatus to determine if any of the alarm bit flags are set. At a minimum, this requires the system to poll the Smart Battery BatteryStatus every 10 seconds at all times the SMBus is active.

### 7.1.24 CycleCount ( $0 \times 17$ )

CycleCount is updated to keep track of the total usage of the battery. CycleCount is increased whenever an amount of charge has been delivered to, or removed from the battery, equivalent to the full capacity.

### 7.1.25 DesignCapacity ( $0 \times 18$ )

Returns the theoretical capacity of a new pack. The DesignCapacity value is expressed in either current or power, depending on the setting of the BatteryMode's CAPACITY_MODE bit.

### 7.1.26 DesignVoltage ( $0 \times 19$ )

Returns the theoretical voltage of a new pack ( mV ).

### 7.1.27 SpecificationInfo (0x1a)

Returns the version number of the Smart Battery specification the battery pack supports.

### 7.1.28 ManufactureDate ( $0 \times 1 \mathrm{~b}$ )

This function returns the date the cell pack was manufactured in a packed integer. The date is packed in the following fashion: (year-1980) * 512 + month * 32 + day.

### 7.1.29 SerialNumber (0x1c)

This function is used to return a serial number. This number, when combined with the ManufacturerName, the DeviceName and the ManufactureDate, will uniquely identify the battery.

### 7.1.30 ManufacturerName (0x20)

This function returns a character array containing the battery manufacturer's name.

### 7.1.31 DeviceName (0x21)

This function returns a character string that contains the battery's name.

### 7.1.32 DeviceChemistry (0x22)

This function returns a character string that contains the battery's chemistry. For example, if the DeviceChemistry function returns "NiMH", the battery pack would contain nickel metal hydride cells. The following is a partial list of chemistries and their expected abbreviations. These abbreviations are not case sensitive.

Lead Acid: PbAc<br>Lithium Ion: LION<br>Nickel Cadmium: NiCd<br>Nickel Metal Hydride: NiMH<br>Nickel Zinc: NiZn<br>Rechargeable Alkaline-Manganese: RAM<br>Zinc Air: ZnAr

### 7.1.33 ManufacturerData (0x23)

This function allows access to the manufacturer data contained in the battery (data).

### 7.1.34 OptionalMfgFunction

The PS501-0901 does not implement this function.

TABLE 7-2: PS501-0901 ALARMS AND STATUS SUMMARY

| Battery Status | Set Condition | Clear Condition |
| :--- | :--- | :--- |
| FULLY_CHARGED bit | Set at End-Of-Charge Condition: <br> Charge FET off <br> AND <br> Any VC(x) input > 4.175V <br> AND <br> IAVG < EOC_IAVG for ChrgCntrITimer <br> number of consecutive counts | RelativeStateOfCharge ( ) < CIrFullyChrg <br> (default RSOC = 80\%) |
| OVER_CHARGED_ALARM bit | Valid EOC | VPACK < Reset TCAVolt |
| TERMINATE_CHARGE_ALARM bit | Charging Temperature ( ) > <br> ChrgMaxTemp (default 60ㅇ) <br> OR <br> FULLY_CHARGED bit = 1 | VPACK < Reset TCAVolt <br> AND <br> Temperature ( ) < ChrgRecTemp = |
| AND |  |  |
| Current ( ) = < 0 |  |  |

### 8.0 PARAMETER SETUP

This section documents all of the programmable parameters that are resident in memory. It includes parameters that are common to the standard PS501-0901 parameter set. The parameter set is organized into the following functional groups:

1. Configuration
2. Calibration
3. Safety
4. Charge and Discharge
5. Capacity

## TABLE 8-1: CONFIGURATION

| Parameter Name |  | Lower Limit | Upper Limit | Typical Value | Operational Description |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Cells | 1 | 0 | 255 | 6 | Number of series cells in the battery pack. |
| Date | 2 | 0 | 0xFFFF | 0x2B7E | SBData value for ManufactureDate. The date of manufacture of the battery pack can be programmed here and retrieved with the SBData ManufactureDate command. <br> Coding: Date $=($ Year-1980 $) \times 512+$ Month $\times 32+$ Day |
| SerialNumber | 2 | 0 | 65535 | 1 | SBData value for SerialNumber. The serial number of the battery pack can be programmed here and retrieved with the SBData SerialNumber command. |
| MFGData | 4 | - | - | 0x0 | SBS string for ManufacturerData. |
| PackResistance | 2 | 0 | 65535 | 65 | Resistance of pack. |
| NullCurr | 1 | 0 | 255 | 3 | A zero zone control is built into the PS501-0901 so that any small inaccuracy doesn't actually drain the fuel gauge, when in fact, the current is zero. For this reason, current less than NullCurr mA in either direction will be measured as zero. |
| Flags1 | 1 | 0 | 255 | b00100110 | Bit coded as follows:  <br> $\frac{\text { Bit }}{7}$ $\frac{\text { Function }}{\text { Enable precharge max current check }}$ <br> 6 Hold charge current = 0 until next discharge <br> 5 Int/Ext temperature <br> 4 Disable Sleep in main Idle mode <br> 3 Require null current for low-voltage Sleep <br> 2 Disable safety GPIO <br> 1 Enable pack resistance <br> 0 Enable Sample mode detect |
| LowCurrError | 1 | 0 | 255 | 0 | Current offset for error calculation. Since the error of the A/D converter is proportional to the level of current it is measuring, the error term can be too low when the current is very low. For this reason, the LowCurrError will compensate the error term for low currents. <br> LowCurrError milliamps are added to the current when factoring in the error. Thus, the error is: <br> Error = (Current + LowCurrError) * CurrError. |
| CurrError | 1 | 0 | 255 | 0 | Current measurement error. This is the error due to the accuracy of the $A / D$ converter to measure and integrate the current, $255=100 \%$. |
| StableCurr | 1 | 0 | 255 | 50 | EOC trigger current deviation level. In order to prevent current spikes from causing a premature taper current trigger, the average current and the instantaneous current must be within StableCurr of each other for the End-Of-Charge to trigger. |
| RelearnLimit | 1 | 0 | 255 | 205 | The maximum relearn limit. The maximum percentage that the FullCapacity can change after a learning cycle, where $255=100 \%$. |

## TABLE 8-1: CONFIGURATION (CONTINUED)

| Parameter <br> Name | \# <br> Bytes | Lower <br> Limit | Upper <br> Limit | Typical <br> Value | Operational Description |
| :--- | :---: | :---: | :---: | :---: | :--- | :--- |
| DesignVPack | 2 | 0 | 65535 | 9000 | SBData value for DesignVoltage. |
| PW1 | 2 | 0 | 65535 | AA4D | First password for the battery pack lock. |
| PW2 | 2 | 0 | 65535 | D4AA | Second password for the battery pack lock. |

TABLE 8-1: CONFIGURATION (CONTINUED)

| Parameter <br> Name | \# <br> Bytes | Lower <br> Limit | Upper <br> Limit | Typical <br> Value | Operational Description |
| :--- | :---: | :---: | :---: | :---: | :--- |
| AgeFactor | 1 | 0 | 255 | 0 | Scale factor for EOD voltage due to aging. |
| PwrUpTimer | 1 | 0 | 255 | 4 | Time during which GPIO are inactive after first <br> power-up. |
| NPermLogCnt | 1 | 0 | 255 | 0 | Counter for logging Faults. |
| NPermLogReg | 1 | 0 | 255 | 0 | Register for logging Faults. |
| ReInitGPIO | 2 | 0 | 65535 | 0 | Register for resetting all GPIO during testing. |
| GPIODelayFlags | 2 | 0 | 65535 | 0 | Positive logic change of GPIO is delayed when upper <br> byte is set. Lower byte maps to GPIO. |
| GPIODelayMS | 1 | 0 | 255 | 0 | GPIO delay in milliseconds when GPIODelayFlags has <br> the delay enabled. |
| MFGName | 10 | - | - | Microchip | SBS string for ManufacturerName. Can be any ASCII <br> string, typically the name of the battery pack <br> manufacturer. Length of string is defined by <br> MFGNameLength. |
| DeviceName | 8 | - | - | PS501- | SBData value for DeviceName. Can be any ASCII <br> string. Length defined by DeviceNameLength. The <br> battery circuit device name can be programmed here <br> and retrieved with the SBData DeviceName command. |
| Chemistry | 8 | - | - | NIMH | SBS data for DeviceChemistry. Can be any ASCII <br> string. Length defined by ChemistryLength. The <br> Chemistry name can be programmed here and <br> retrieved with the SBData DeviceChemistry command. |
| ParamVersion | 1 | 0 | 255 | 0 | EEPROM version control number. <br> KeyByte |
| 1 | $0 x 0$ | $0 x F F$ | $0 x D A$ | EE KeyByte must be 0xDA before P5 will exit <br> Bootloader mode. |  |

## TABLE 8-2: CALIBRATION

| Parameter Name | \# Bytes | Lower Limit | Upper Limit | Typical Value | Operational Description |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Config1 | 1 | 0x0 | 0xFF | 0x69 | Bootload configuration. |
| OSCTrim | 1 | 0 | 255 | 200 | RC oscillator trimming. |
| BGCal | 1 | 0 | 255 | 11 | Band gap voltage calibration factor. |
| RefCal | 1 | 0 | 255 | 19 | Reference voltage calibration factor. |
| CFCurr | 2 | 0 | 65535 | 6844 | Correction Factor for Current. Adjusts the scaling of the sense resistor current measurements. Used to calibrate the measurement of current at the RSHP and RSHN input pins. This is set for the size of the current sense resistor. |
| COCurr | 1 | -128 | 127 | -12 | Correction Offset for Current. This is the value the A/D reads when zero current is flowing through the sense resistor. |
| COD | 1 | -128 | 127 | -12 | Correction Offset Deviation. Offset value for the auto-zero calibration of the current readings. <br> SBData Current [mA] = (I_A/D - COCurr - COD) x CFCurr/16384 <br> Calibration: CFCurr $=(($ Ammeter $[m A] \times 16384)-8192) /$ <br> (Current - I_A/D at OCV) |
| CFTempE | 2 | 0 | 65535 | 1300 | Correction Factor for Temperature. Adjusts the scaling of temperature measured across an external thermistor at the VNTC input pin. |
| COTempE | 1 | -128 | 127 | -2 | Correction Offset for Temperature. Offset = 0 used for temperature measurement using internal temperature sensor. |
| CFTempl | 2 | 0 | 65535 | 23800 | Correction Factor for Temperature. Adjusts the scaling of temperature measured from the internal temperature sensor. Calibration: New CFTemp = Old CFTemp $\times$ (Thermometer [ $\left.{ }^{\circ} \mathrm{C}\right] /$ SBData Temperature [ $\left.{ }^{\circ} \mathrm{C}\right]$ ) <br> Note: SBData Temperature is reported in $0.1^{\circ} \mathrm{K}$ normally. It must be converted to ${ }^{\circ} \mathrm{C}$ for this equation. |
| COTempl | 2 | -32768 | 32767 | -11375 | Correction Offset for Temperature. Offset $=0$ used for temperature measurement using internal temperature sensor. |
| CFVPack | 2 | 0 | 65535 | 20045 | Correction Factor for Pack Voltage. Adjusts the scaling of the pack voltage measurements. Used to calibrate the measurement of pack voltage. |
| COVPack | 1 | -128 | 127 | 0 | Correction Offset for Voltage. Offset factor used for pack voltage reading. |
| CalStatus | 1 | 0 | 255 | b00000000 | $\frac{\text { Bit }}{7}$ Function <br> Factory calibrated  <br> 6 EE/Flash downloaded <br> 5 RC oscillator <br> 4 External temperature <br> 3 Internal temperature <br> 2 Current <br> 1 Pack voltage <br> 0 Cell voltages <br>   <br> $0=$ Not calibrated  <br> $1=$ Calibrated  |

TABLE 8-3: SAFETY

| Parameter <br> Name | \# <br> Bytes | Lower <br> Limit | Upper <br> Limit | Typical <br> Value | Operational Description |
| :--- | :---: | :---: | :---: | :---: | :--- | :--- |
| RemCapAI | 2 | 0 | 65535 | 440 | SBData value for RemainingCapacityAlarm. The SBData <br> specification requires a default of DesignCapacity/10 for this <br> value. When the remaining capacity calculation reaches the <br> value of RemCapAI, the REMAINING_CAPACITY_ALARM bit <br> will be set in the BatteryStatus register and an alarm broadcast <br> to the host will occur if alarm broadcasts are enabled. |
| RemTimeAI | 2 | 0 | 65535 | 10 | SBData value for RemainingTimeAlarm. SBData requires a <br> default of 10 minutes for this value. When the RunTimeToEmpty <br> calculation reaches the value of RemTimeAI, the <br> REMAINING_TIME_ALARM bit in BatteryStatus will be set. |
| MaxTemp | 1 | 0 | 65535 | 112 | Maximum temperature measured (including external and <br> internal sensor). Coded value $=(C e l s i u s ~ * ~ 10 ~+~ 200) / 4 . ~ T h i s ~ i s ~$ |
| where the PS501-0901 keeps track of the highest |  |  |  |  |  |
| temperature it has measured. |  |  |  |  |  |

## TABLE 8-4: CHARGE AND DISCHARGE

| Parameter Name | \# Bytes | Lower Limit | Upper Limit | Typical Value | Operational Description |
| :---: | :---: | :---: | :---: | :---: | :---: |
| ChrgVolt | 2 | 0 | 65535 | 65535 | This is the voltage required by the battery during normal charging. |
| ChrgCurr | 2 | 0 | 65535 | 3500 | This is the full charging current that the battery requires during normal charging. It can be broadcasted to the charger or read from the PS501-0901. |
| ChrgVoltOff | 2 | 0 | 65535 | 0 | The voltage requested by the battery when charging is complete. |
| ChrgCurrOff | 2 | 0 | 65535 | 100 | Trickle charging current. This is a small amount of current that the charger should deliver when full charging needs to be halted temporarily due to high temperature. |
| PrechargeCurr | 2 | 0 | 65535 | 300 | Precharge nominal current. |
| ChrgMinTemp | 2 | 0 | 65535 | 50 | Low temperature threshold, charging coded value $=\left(\right.$ Temp $\left.\left[{ }^{\circ} \mathrm{C}\right] * 10+200\right) / 4$. When charging, if the temperature is less than ChrgMinTemp, then ChargingCurrent is set to ChrgCurrOff and ChargingVoltage is set to ChrgVoltOff. |
| ChrgMaxTemp | 2 | 0 | 65535 | 175 | Temperature threshold when charging, coded value $=\left(\right.$ Temp $\left.\left[{ }^{\circ} \mathrm{C}\right] * 10+200\right) / 4$. When the temperature exceeds ChrgMaxTemp and the battery is charging, then ChargingCurrent is set to ChrgCurrOff and ChargingVoltage is set to ChrgVoltOff. |
| PrechargeTemp | 2 | 0 | 65535 | 50 | Precharge temperature, coded value $=\left(\right.$ Temp $\left.\left[{ }^{\circ} \mathrm{C}\right] * 10+200\right) / 4$. This is the temperature under which precharging should occur. |
| PrechargeVPack | 2 | 0 | 65535 | 7000 | Precharge pack voltage. This is the voltage under which precharging should occur. |
| PrechargeMax | 2 | 0 | 65535 | 500 | Precharge max current. |
| ConfigEOC | 1 | 0 | 255 | b11001111 | Bit coded as follows:  <br> $\frac{\text { Bit }}{7}$ $\frac{\text { Function }}{\text { EOC on EOCTimer }}$ <br> 6 EOC on TCAVolt <br> 5 Limit remcap to FCC <br> 4 Set overcharge alarm at EOC <br> 3 Load remcap with FCC at EOC <br> 2 EOC on RSOC $>$ MaxSOC <br> 1 EOC on -dV <br> 0 EOC on dT/dt |
| ConfigEOD | 1 | 0 | 255 | b11111100 | Bit coded as follows:  <br> $\frac{\text { Bit }}{7}$ $\frac{\text { Function }}{\text { Evaluate EOD1 on fixed voltage (else look-up table) }}$ <br> 6 Set fully charged bit on EOD1 <br> 5 Set capacity to residual capacity value on VEOD1 <br> 4 Set TERMINATE_DISCHARGE_ALARM on <br> 3 VEOD1 (0 on VEOD2) <br> 2 Learn FCC at VEOD1 <br> 1 TERMINATE_DISCHARGE_ALARM on EOD2 <br> 0 Set capacity to zero at VEOD2 |
| CIrFullyDischrg | 1 | 0 | 255 | 10 | Clear fully discharged bit (\%). Once fully discharged bit is set, it will stay set until capacity rises above this value, typically $10 \%$. |

TABLE 8-4: CHARGE AND DISCHARGE (CONTINUED)

| Parameter Name | $\begin{array}{\|c\|} \hline \# \\ \text { Bytes } \end{array}$ | Lower Limit | Upper Limit | Typical Value | Operational Description |
| :---: | :---: | :---: | :---: | :---: | :---: |
| EOCVolt | 2 | 0 | 65535 | 7000 | Pack voltage (mV) at which the algorithm will start to monitor the selected EOC options to determine the EOC point. |
| ClrFullyChrg | 1 | 0 | 255 | 90 | Clear fully charged bit (\%). Once the FULLY_CHARGED bit is set, it will remain set until the battery has discharged to less than $90 \%$. |
| EOD1Voltage | 2 | 0 | 65535 | 6000 | First End-Of-Discharge voltage (mV) point if using a fixed voltage instead of look-up table. |
| RelearnCurrLim | 2 | 0 | 65535 | 10000 | Value of measured current that prevents a capacity relearn from occurring when a terminate discharge alarm condition is reached at End-Of-Discharge (EOD). A learning cycle will happen when the battery discharges from fully charged, all the way to fully discharged, with no charging in between and the discharge current never exceeds RelearnCurrLim (Example: 3000). A relearn will only occur if current does not exceed 3000 mA . |
| RelearnMaxErr | 2 | 0 | 65535 | 300 | Maximum error for learning FullCapacity. The FullCapacity will not be learned after a learning cycle if the error is too great. |
| EOD1Recheck | 1 | 0 | 255 | 2 | Number of operating cycles where the voltage must be below the selected End-Of-Discharge voltage for a valid EOD1. |
| EOD2Recheck | 1 | 0 | 255 | 0 | Number of operating cycles where the voltage must be below the selected End-Of-Discharge voltage for a valid EOD2. |
| EOD2Voltage | 2 | 0 | 65535 | 5400 | Second End-Of-Discharge voltage (mV) point. |
| NChangeState | 1 | 0 | 255 | 2 | State change delay filter. Delays the change between "charge increasing" state and "charge decreasing" state based on current direction. To avoid problems with current spikes in opposite directions, a delay filter is built in to control when to change from charging status to discharging status. The current must change directions and stay in the new direction for this many operational cycles before the status is changed and capacity is increased or decreased as a result of the new current direction. |
| ADLNearEmpty | 1 | 0 | 255 | 6500 | Pack voltage ( mV ) at which A/D changes to a measurement list optimized for near EOD. |
| ADLNearFull | 1 | 0 | 255 | 7000 | Pack voltage ( mV ) at which A/D changes to a measurement list optimized for near EOC. |
| RemCapDelta | 1 | 0 | 255 | 1 | Maximum change in remaining capacity (mAh) per measurement period during charge. |
| EOCTimeout | 2 | 0 | 65535 | 35156 | If selected as an EOC termination method, an EOC condition will be valid when charge time exceeds this value (units: 1.024 seconds). |
| MaxDischTemp | 1 | 0 | 255 | 255 | Temperature threshold when discharging, coded value $=($ Celsius * $10+200) / 4$. When discharging, if the temperature exceeds this value, ChargingCurrent is set to ChrgCurrOff and ChargingVoltage is set to ChrgVoltOff. |
| EOCSample | 1 | 0 | 255 | 58 | Time (units: 1.024 seconds) between EOC condition evaluation. |
| EOCdTTemp | 1 | 0 | 255 | 3 | Minimum temperature change between EOCSample to cause a temperature EOC (units: $0.4^{\circ} \mathrm{C}$ ). |
| EOCdTSOC | 1 | 0 | 255 | 95 | Relative SOC is set to this value after a full charge temperature EOC condition occurs (\%). |

## TABLE 8-4: CHARGE AND DISCHARGE (CONTINUED)

| Parameter <br> Name | \# <br> Bytes | Lower <br> Limit | Upper <br> Limit | Typical <br> Value | Operational Description |
| :--- | :---: | :---: | :---: | :---: | :--- |
| EOCdVDelay | 1 | 0 | 255 | 5 | Delay, after Start-Of-Charge, before full charge -dV EOC <br> conditions can be considered (minutes). |
| EOCdVVoltDrop | 2 | 0 | 65535 | 60 | Minimum voltage drop change to cause a -dV EOC. <br> Typically, 10 mV per series cell. |
| EOCdVCurr | 2 | 0 | 65535 | 1000 | Minimum current (mA) required for -dV EOC to be <br> considered. |
| EOCChrgMaxSOC | 1 | 0 | 255 | 120 | Overcharge EOC (\%). If the Start-Of-Charge exceeds this <br> value (\%), End-Of-Charge will be triggered. |

TABLE 8-5: CAPACITY

| Parameter Name | $\begin{gathered} \# \\ \text { Bytes } \end{gathered}$ | Lower Limit | Upper Limit | Typical Value | Operational Description |
| :---: | :---: | :---: | :---: | :---: | :---: |
| InitialCap | 2 | 0 | 65535 | 2048 | The initial capacity (mAh) of the battery. When the PS501-0901 is first powered up and initialized, remaining capacity will take the value programmed into InitialCap to compute relative State-Of-Charge percentage. |
| ConfigCap | 1 | 0 | 255 | Ob11010000 |  |
| EOD1Cap | 2 | 0 | 65535 | 0 | The capacity ( mAh ) that remains in the battery at VEOD1. This is typically a small amount used to power a shutdown sequence for the system. |
| FullCapacity | 2 | 0 | 65535 | 3700 | Learned value of battery capacity (mAh). Used for SBData value of FullChargeCapacity. This is a learned parameter, which is the equivalent of all charge counted from fully charged to fully discharged, including self-discharge and error terms. This is reset after a learning cycle and used for remaining capacity and relative State-Of-Charge calculations. |
| CapErrReset | 2 | 0 | 65535 | 0 | Value to set MaxError to at EOD. |
| RLCycles | 1 | 0 | 255 | 2 | The number of initial cycles without RelearnLimit. The initial number of cycles where RelearnLimit is not active. FullCapacity can vary greatly with the first learning cycle, since the initial capacity may not be correct, thus this should be set to at least ' 2 '. |
| DesignCapacity | 2 | 0 | 65535 | 3700 | SBData value for DesignCapacity. This is the capacity (mAh) loaded into the FullChargeCapacity upon power-up. |
| mWhConv | 2 | 0 | 65535 | 20000 | Constant for conversion from mAh to mWh. |

### 9.0 ELECTRICAL CHARACTERISTICS

## TABLE 9-1: ABSOLUTE MAXIMUM RATINGS

| Symbol | Parameter | Min | Max | Units |
| :--- | :--- | :---: | :---: | :---: |
| VCX | Voltage at any VC(x) pin | -0.5 | 18.5 | V |
| VPIN | Voltage directly at any pin (except VC(x)) | -0.5 | 7.0 | V |
| TBIAS | Temperature under Bias | -20 | 85 | ${ }^{\circ} \mathrm{C}$ |
| Tstorage | Storage Temperature (package dependent) | -35 | 125 | ${ }^{\circ} \mathrm{C}$ |

Note 1: These are stress ratings only. Stress greater than the listed ratings may cause permanent damage to the device. Exposure to absolute maximum ratings for an extended period may affect device reliability. Functional operation is implied only at the listed operating conditions below.


| Symbol | Characteristic | Min | Typ | Max | Units | Condition |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Vsupply | Supply Voltage - Applied to VC(1) | 5.6 | - | 18.0 | V |  |
| VdDA | Supply Voltage - Output from Internal Regulator on Vdda pin | 4.5 | 5.0 | 5.5 | V | (Note 1) |
| IDD | Instantaneous Supply Current | - | 375 | 400 | $\mu \mathrm{A}$ | (Note 2) |
| IDDRUN | Average Supply Current - Run Mode | - | 300 | 385 | $\mu \mathrm{A}$ | A/D active (Note 2) |
| IDDINS | Inactive Supply Current - Sample Mode | - | 225 | 250 | $\mu \mathrm{A}$ | A/D inactive (Note 2,3) |
| IDDSLEEP | Average Supply Current - Sleep Mode | - | 12 | 25 | $\mu \mathrm{A}$ | Sleep mode (Note 2) |
| IWAKE | Wake-up Current Threshold from Sleep Mode Voltage across Sense Resistor | 2.50 | 3.75 | 5.00 | mV |  |
| VIL | Input Low Voltage - GPIO(7-0) | - | - | 0.2 * VDDD | V |  |
| VIH | Input High Voltage - GPIO(7-0) | 0.8 * VDDD | - | - | V |  |
| IIL-IOPU | GPIO Input Low Current - Pull-up Mode | - | 50 | - | $\mu \mathrm{A}$ |  |
| IIH-IOPD | GPIO Input High Current - Pull-down Mode | - | 25 | - | $\mu \mathrm{A}$ |  |
| IL | Leakage Current - GPIO pins Programmed as Outputs | - | 1 | 2 | $\mu \mathrm{A}$ |  |
| VoL | Output Low Voltage for GPIO(7-0) | - | - | 0.4 | V | $\mathrm{IOL}=0.5 \mathrm{~mA}$ |
| Vон-ı | Output High Voltage for GPIO(7-0) (non-LED mode) | 2.0 | - | - | V | $\mathrm{IOH}=100 \mu \mathrm{~A}$ |
| Voh-LED | Output High Voltage for GPIO(7-0) (LED mode) | 2.0 | - | - | V | $\mathrm{IOH}=10 \mathrm{~mA}$ (Note 4) |
| VSR | Sense Resistor Input Voltage Range | -152 | - | 152 | mV |  |
| VNTC | Thermistor Input Voltage Range | 0 | - | 152 | mV |  |
| Vreft | NTC Reference Voltage Output at Vreft pin | - | 150 | - | mV |  |
| VIL-SMB | Input Low Voltage for SMBus pins | -0.5 | - | 0.8 | V |  |
| VIH-SMB | Input High Voltage for SMBus pins | 2.0 | - | 5.5 | V |  |
| Vol-SmB | Output Low Voltage for SMBus pins | - | - | 0.4 | V | IPULLUP $=350 \mu \mathrm{~A}$ |
| Voh-Smb | Output High Voltage for SMBus pins | 2.1 | - | 5.5 | V |  |
| IPULLUP-SMB | Current through Pull-up Resistor or Current Source for SMBus pins | 100 | - | 350 | $\mu \mathrm{A}$ |  |
| ILEAK-Smb | Input Leakage Current - SMBus pins | - | - | $\pm 5$ | $\mu \mathrm{A}$ |  |

Note 1: VREG is the on-chip regulator voltage. It is internally connected to the analog supply voltage and is output on the Vdda pin.
2: Does not include current consumption due to external loading on pins.
3: Sample mode current is specified during an A/D inactive cycle. Sample mode average current can be calculated using the formula: Average Sample Mode Supply Current = (IDDRUN + $\left.(n-1)^{*} \operatorname{IDDINS}\right) / n$; where " $n$ " is the programmed sample rate.
4: During LED illumination, currents may peak at 10 mA , but average individual LED current is typically 5 mA (using low-current, high brightness devices).

TABLE 9-3: AC CHARACTERISTICS (TA $=-20^{\circ} \mathrm{C}$ TO $+85^{\circ} \mathrm{C}$; VREG (INTERNAL) $=+3.3 \mathrm{~V} \pm 10 \%$ )

| Symbol | Characteristic | Min | Typ | Max | Units | Condition |
| :--- | :--- | :---: | :---: | :---: | :---: | :---: |
| dfRC | Internal RC Oscillator Frequency | - | 512 | - | kHz |  |
| $\mathrm{t}_{\text {CONV }}$ | A/D Conversion Measurement Time, n-bit + sign | - | $2^{\mathrm{n} / \mathrm{ff} / \mathrm{D}}$ | - | ms |  |

TABLE 9-4: AC CHARACTERISTICS: SMBus ( $\mathrm{TA}=-20^{\circ} \mathrm{C}$ TO $+85^{\circ} \mathrm{C}$; VREG (INTERNAL) $=+3.3 \mathrm{~V} \pm 10 \%$ )

| Symbol | Characteristic | Min | Typ | Max | Units | Condition |
| :--- | :--- | :---: | :---: | :---: | :---: | :---: |
| fSMB | SMBus Clock Operating Frequency | $<1.0$ | - | 100 | kHz | Slave mode |
| fSMB-MAS | SMBus Clock Operating Frequency | 50 | $\mathrm{fRC} / 8$ | 68 | kHz | Master mode (Note 1) |
| tBUF | Bus Free Time between Start and Stop | 4.7 | - | - | $\mu \mathrm{s}$ |  |
| tSHLD | Bus Hold Time after Repeated Start | 4.0 | - | - | $\mu \mathrm{s}$ |  |
| tSU:STA | Setup Time before Repeated Start | 4.7 | - | - | $\mu \mathrm{s}$ |  |
| tSU:STOP | Stop Setup Time | 4.0 | - | - | $\mu \mathrm{s}$ |  |
| tHLD | Data Hold Time | 300 | - | - | $\mu \mathrm{s}$ |  |
| tSETUP | Data Setup Time | 250 | - | - | $\mu \mathrm{s}$ |  |
| tTIMEOUT | Clock Low Time-out Period | 10 | - | 35 | ms | (Note 2) |
| tLOW | Clock Low Period | 4.7 | - | - | $\mu \mathrm{s}$ |  |
| tHIGH | Clock High Period | 4.0 | - | 50 | $\mu \mathrm{~s}$ | (Note 3) |
| tLOW:SEXT | Message Buffering Time | - | - | 10 | ms | (Note 4) |
| tLOW:MEXT | Message Buffering Time | - | - | 10 | ms | (Note 5) |
| tF | Clock/Data Fall Time | - | - | 300 | ns | (Note 6) |
| tR | Clock/Data Rise Time | - | - | 1000 | ns | (Note 6) |

Note 1: Used when broadcasting AlarmWarning, ChargingCurrent, and/or ChargingVoltage values to either a SMBus host or a SMBus Smart Battery Charger. This is only used when the PS501-0901 becomes an SMBus master for these functions. The receiving (slave) device may slow the transfer frequency. See the SMBus tutorial in "PS401 User's Guide" (DS40239) for additional information.
2: The PS501-0901 will time-out when the cumulative message time defined from Start-to-Ack, Ack-to-Ack or Ack-to-Stop exceeds the value of ttimeout, min. of 25 ms . The PS501-0901 will reset the communication no later than tTIMEOUT, max. of 35 ms .
3: thigh max. provides a simple, ensured method for devices to detect bus Idle conditions.
4: tLow:SEXT is the cumulative time a slave device is allowed to extend the clock cycles in one message from the initial start to the stop.
5: tLOW:MEXT is the cumulative time a master device is allowed to extend its clock cycles within each byte of a message as defined from Start-to-Ack, Ack-to-Ack or Ack-to-Stop.
6: Rise and fall time is defined as follows:
$\mathrm{tR}=\left(\mathrm{VIL}_{\text {MAX }}-0.15\right)$ to $\left(\mathrm{VIH}_{\text {MIN }}+0.15\right)$
$\mathrm{tF}=0.9 \mathrm{VDD}$ to $\left(\mathrm{VIL}_{\text {max }}-0.15\right)$

TABLE 9-5: A/D CONVERTER CHARACTERISTICS (TA = $-20^{\circ} \mathrm{C}$ TO $+85^{\circ} \mathrm{C}$;
VREG (INTERNAL) $=+3.3 \mathrm{~V} \pm 10 \%$ )

| Symbol | Characteristic | Min | Typ | Max | Units | Condition |
| :--- | :--- | :---: | :---: | :---: | :---: | :--- |
| ADRES | A/D Converter Resolution | 8 | - | 15 | bits | (Note 1) |
| VADIN | A/D Converter Input Voltage Range <br> (internal) | -152 | - | 152 | mV | Differential mode (Note 2) |
|  | 0 | - | 300 | mV | Single-Ended mode (Note 2) |  |
| EVGAIN | Supply Voltage Gain Error | - | - | 0.100 | $\%$ |  |
| EVOFFSET | Compensated Offset Error | - | - | 0.100 | $\%$ |  |
| ETEMP | Temperature Gain Error | - | - | 0.100 | $\%$ |  |
| EINL | Integrated Nonlinearity Error | - | - | 0.004 | $\%$ |  |

Note 1: Voltage is internal at A/D converter inputs. VSR and VNTC are measured directly. VC(x) inputs are measured using internal level translation circuitry that scales the input voltage range appropriately for the converter.

FIGURE 9-1: SMBus AC TIMING DIAGRAMS


Note: $\mathrm{SCL}_{\mathrm{ACK}}$ is the Acknowledge related clock pulse generated by the master.

TABLE 9-6: $\quad$ SILICON TIME BASE CHARACTERISTICS (TA $=-20^{\circ} \mathrm{C}$ TO $+85^{\circ} \mathrm{C}$;
VREG (INTERNAL) $=+5.0 \mathrm{~V} \pm 10 \%$ )

| Symbol | Characteristic | Min | Typ | Max | Units | Condition |
| :--- | :--- | :---: | :---: | :---: | :---: | :--- |
| ETIME | Silicon Time Base Error | - | - | 0.25 | $\%$ | Bias Resistor RosC <br> Tolerance $=1 \%, \mathrm{TL}= \pm 100 \mathrm{PPM}$ |

### 10.0 PACKAGING INFORMATION

### 10.1 Packaging Marking Information

28-Lead SSOP


Example


Legend: XX ...X Customer specific information*
Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01’)
NNN Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

* Standard device marking consists of Microchip part number, year code, week code, and traceability code. For device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.


### 10.2 Package Details

The following sections give the technical details of the packages.

## 28-Lead Plastic Shrink Small Outline (SS) - 209 mil Body, 5.30 mm (SSOP)



| Units |  | INCHES |  |  | MILLIMETERS* |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Dime |  | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | 28 |  |  | 28 |  |  |
| Pitch | p |  | . 026 |  |  | 0.65 |  |
| Overall Height | A | - | - | . 079 | - | - | 2.0 |
| Molded Package Thickness | A2 | . 065 | . 069 | . 073 | 1.65 | 1.75 | 1.85 |
| Standoff | A1 | . 002 | - | - | 0.05 | - | - |
| Overall Width | E | . 295 | . 307 | . 323 | 7.49 | 7.80 | 8.20 |
| Molded Package Width | E1 | . 009 | . 209 | . 220 | 5.00 | 5.30 | 5.60 |
| Overall Length | D | . 390 | . 402 | . 413 | 9.90 | 10.20 | 10.50 |
| Foot Length | L | . 022 | . 030 | . 037 | 0.55 | 0.75 | 0.95 |
| Lead Thickness | c | . 004 | - | . 010 | 0.09 | - | 0.25 |
| Foot Angle | $f$ | $0^{\circ}$ | $4^{\circ}$ | $8^{\circ}$ | $0^{\circ}$ | $4^{\circ}$ | $8^{\circ}$ |
| Lead Width | B | . 009 | - | . 015 | 0.22 | - | 0.38 |

*Controlling Parameter
Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed . 010 " ( 0.254 mm ) per side.

JEDEC Equivalent: MO-150
Drawing No. C04-073

PS501-0901

NOTES:

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